Paper ID	Authors	Title	Track	Decision
8	Jiahao Liu, Xuemei Zhong, Lijin Qiu, Fangzhou Chen, Jixi Huang, Hongtao Chen and Hao Zhao	Characterization of Mechanical Deformation Resistance of a Novel Interconnection Solder Based on Porous Copper-Filled SAC305 for Deep Space Exploration	Packaging Materials & Processes	ACCEPT
9	Weiming Li, Shusen Fang, Haodong Pan and Lili Ma	Application of 3D X-ray Microscopy in the Identification of Board-level Interconnection Defects	Quality & Reliability	ACCEPT
10	Ruijiao Qin, Qinlong Li, Xi Liu and Anxue Zhang	A High-Integration D-Band Terahertz Radiator Enabled by 3D Metal Micro-Coaxial Technology and SiP Integration	RF Electronic Packaging	ACCEPT
11	Yanfei Zhao, Zhiyuan Wang, Yan Shen, Yanlan Xu, Lei Zhu and	Failure Investigation of Halogen-Induced Corrosion on Aluminum Bond Pads Using SEM, AES and TOF-SIMS	Quality & Reliability	ACCEPT
13	Na Ya, Qidong Wang, Xin Li, Che Song, Xiangan You and Zhidan Fang	A Unified Single-Phase Equivalent Circuit for Multi-Phase Buck Converters Considering Phase-Overlap Effect	Power Electronics & Energy Electronics	ACCEPT
15	Hungyuan Li, Fa-Chuan Chen, Bing-Yeh Lin, HI Chen, Bo-Kuan	Thermal and Warpage Simulation with Validation of Large Exposed-Die FCCSP for Automotive SoCs	Packaging Design & Modeling	ACCEPT
16	Longbing Yi, Xuefeng Zheng, Wen Hong, Shunyu Wang, Kang Li, Vazgen Melikyan, Danmei Lin, Xiaohua Ma and Yue Hao	Integration of superlattice-based thin-film thermoelectric module in β-Ga_2O_3 Schottky barrier diodes for simultaneous cooling and power generation	Power Electronics & Energy Electronics	ACCEPT
17	Zhuotong Li, Caixia Liang, Fangzhou Chen, Rui Chen, Hao Zhao and Jiahao Liu	Design and Predictive Methodology for Submicron TSV Interconnect Structures Based on Thermo-Mechanical Coupling	Advanced Packaging	ACCEPT
18	Smit Golakiya	Ion-Engineered CVD Diamond Surfaces: Tribological Adaptation for Multi-Environment Self-Lubrication in Vacuum, Nitrogen, and Ambient	Emerging Technologies	ACCEPT
21	Lois Liao, Penny Long, Younan Hua, Xi Zhang, Xiaomin Li and	Application of deuterium oxide (D_2O) isotope tracer technique for a semiconductor die failure analysis	Quality & Reliability	ACCEPT
22	Jing Xuan, Derk Song, Stuart Lv, X.W. Wu, Xiaoming Yu and Kai Xu	A Unified Data Pipeline and Adaptive Machine Learning Framework for Wire Bonding Defect Prevention and Quality Assurance	Advanced Manufacturing	ACCEPT
25	Qi Tang, Ying Zhao, Ming Xiao, Zhiqi Wang and Weigang Yao	A Thermal Network Model for Quickly Predicting the Temperature of Multi Heat Source Chips	Packaging Design & Modeling	ACCEPT

26	Chu Tang, Zhen Chen, Ke Li and Lei Wang	Effects of substrate material and solder bump structure on flip-chip interconnect quality in 2.5D NPO packaging	Interconnection Technologies	accept?
29	Wenliang Qi, Zhaoyang Xue and Yang Xu	Thermo-Electro-Mechanical Coupling Life Prediction for Solder Joints in Avionics Devices CBGA Components	Quality & Reliability	ACCEPT
30	Yixue Zhu, Hongwei Bao, Zexin Li, Yutai Su, Chaofan Zeng and Fei Ma	Ion migration and dendrite growth in electrochemical migration failure of copper wires in printed circuit boards	Interconnection Technologies	accept?
31	Yongchao Luo, Xingshou Pang, Chao Ma and Xiaolong	Corner Wire Sweep Improvement for HDQFP Package	Packaging Materials &	ACCEPT
32	Lu Tao, Jiang Xie and Pan Haodong	The Effect of Solder Die Attach Voids on the Junction-to-case Thermal Resistance of MOSFET Packages	Quality & Reliability	ACCEPT
34	Ruijie Liu, Xinyuan Wang, Yuhao Cao, Siyu Chen, Yiqian Huang and Yun Mou	A Digital Optimization Framework for Thermal and Mechanical Performance of SiC Power Module Packaging	AI-Enabled Packaging Technologies	ACCEPT
35	Chao Ma, Xingshou Pang, Yongchao Luo and Jinzhong Yao	Unit warpage research for improvement of HDQFP Coplanarity	Packaging Materials & Processes	ACCEPT
36	Wenxue Dai, Fangcheng Wang, Qiang Liu, Wenbo Zhao, Xuefan	A Novel Mid-infrared Laser Debonding in Advanced Wafer-level Packaging	Advanced Packaging	ACCEPT
37	Zhi Jiang	Biocompatible ultrathin devices interfacing with organs	Emerging Technologies	ACCEPT
38	Yiliang Gao and Lijia Liu	Design and synthesis of a novel active ester curing agent modified with hydrocarbon resin and its application in the field of low dielectric resin	Packaging Materials & Processes	ACCEPT
39	Jingyi Lan, Yu Liu and Yuanxin Ding	Torsional stress analysis and optimization of CSP solder joints with three dispensing methods under thermal power conditions	Quality & Reliability	ACCEPT
40	Yuan Zou	Low-temperature pressureless sintering of surface modified non-dewetting Cu@Ag bimodal conductive paste for electronic	Packaging Materials & Processes	ACCEPT
41	Zhiyan Guo, Zhaoling Huang, Hao Zhou, Kaile Xu, Hao Wei, Ju	Micro-Spike Array Pinning Regulation for Self-Healing and Mechanical Stability of Liquid Metal Flexible Circuits	Emerging Technologies	ACCEPT
42	Xiaojian Liu, Fang Yu, Ying Ding and Xiuli Wang	Random Vibration Analysis and Reliability Evaluation of CQFP Packaged Devices with Different Shoulder Widths	Quality & Reliability	ACCEPT
43	Liuyun Ding, Zhuo Pang, Haidong Yan and Meiyu Wang	Effect of Polyethylene Glycol Molecular Weight on the Die-Attach Performance of Pressureless Silver Sintering Paste	Packaging Materials & Processes	ACCEPT

44	Younan Hua	OSAT Characterization Techniques for Quality Control and Enhancement of Aluminum Bondpads in Wafer Fabrication	Quality & Reliability	ACCEPT
45	Wenbo Zhao, Junbo Zang, Ping He, Qiang Liu, Fangcheng Wang,	A Novel UV Laser Debonding Process Based on Single-Layer Temporary Bonding Adhesive for Advanced Packaging	Advanced Packaging	ACCEPT
47	Miao Li, Xiaowei Sun, Song Huidong, Jiajia Zou and Zhaojun Yang	Study on Board-Level Assembly Reliability of CBGA Microwave	Quality & Reliability	ACCEPT
48	Gan Jisong, Wang Zihan, Zhang Yingjie, Shen Shangluan, Chengcheng Chen and Gang Zhu	Failure Analysis of Stress Corrosion Cracking in a PCB Connector Pin under Synergistic Residual Stress and Corrosive Environment in Floating Hydropower Service	Quality & Reliability	ACCEPT
50	Xiaoliang Zhang, Jianbo Xue and Zhaoqing Lu	Multi-Functional Low-Voltage Inverter Integrated System-in-Package for Joint Module Controller	Power Electronics & Energy Electronics	ACCEPT
51	Huang Yueyue, Liang Guancheng, Wu Jianyu, Chen Fangzhou,	Construction and Application Validation of the Performance Index System for Chip-Level Thermal Interface Materials	Advanced Manufacturing	ACCEPT
52	Zihan Wang, Jihua Zhang, Zhen Fang, Jinxu Liu, Shuqi Li, Borui Li, Mingcheng Chen, Wenlei Li and Wanli Zhang	Hybrid Bonding Technology for Glass Substrate Interconnection	Interconnection Technologies	reject?
53	Lihao Ou, Xiangan You, Yang Yang, Che Song and Qidong	A Review of High Current Density Power Modules	Power Electronics &	ACCEPT
54	Zhou Yang, Han Xu, Lang Chen, Jianyu Du, Chi Zhang and Wei Wang	A Thermal Isolation Method Based on “Parylene-Kirigami” Structure for Silicon-Based 2.5D Heterogeneous Integration Systems	Advanced Packaging	ACCEPT
55	Zhicheng Liu, Gang Mou and Qiuchen Ma	Inhibition of interfacial Kirkendall voids in Cu/In joint via nanotwinned copper	Packaging Materials & Processes	ACCEPT
58	Jiaxing Wang	Process Optimization and Reliability Assessment of Indium-Based Solid-State Bonding for Superconducting Quantum Chip Interconnections	Emerging Technologies	ACCEPT
59	Yanhao Yu	Soft Electronic Packaging	Emerging Technologies	ACCEPT
60	Weijie Wu, Yiting Han, Haidong Yan and Meiyu Wang	Guidance for Electric-Field Grading Using A Nonlinear Conductivity Encapsulant for 10 kV power Module Packaging	Power Electronics & Energy Electronics	ACCEPT
62	Si Chen, Xiaofeng Yang, Bingxu Ma, Peijiang Liu, Wanchun Tian and Ziyang Wang	Electromigration Reliability Characterization and Physical Model Development for TSVs	Advanced Packaging	ACCEPT
63	Yuqi Su, Tian Yu, Xin Chen and Shiwei Huang	Design of N77 Band IPD Filter Based on Silicon Carbide Substrate	RF Electronic Packaging	ACCEPT

64	Guihan Hu, Yunyou Liu and Yuna Xuan	Two-Step Electroplating for Void-Free Filling of Large-Size, High-Aspect-Ratio Through Glass Via (TGV)	Interconnection Technologies	ACCEPT
65	Siyuan Lin, Yang Tang, Shiyu Wang, Jian Wang, Shaoqiang Jiang, Fugang Nie, Yao Zhang and Jian Zhou	Comparative Study on High-Temperature Aging Behavior of SIBAC and SAC305 Solders	Packaging Materials & Processes	ACCEPT
66	Shi-Yu Liu, Kai Zhao, Qian-Jin Huang, Dan-Ting Li, Zhi-Hua Yang and Shu-Ying Ma	A Physics Informed Neural Network (PINN) Model for Fan-Out Package Junction-to-Case Thermal Resistance Prediction	AI-Enabled Packaging Technologies	ACCEPT
67	Yanyan Xu, Bin Xie and Mingxiang Chen	Electrospun stretchable BNNS/PVA composite film for efficient thermal management of flexible electroncis	Emerging Technologies	ACCEPT
68	Lang Chen, Chi Zhang and Wei Wang	Process-Integrated Co-Optimization(PICO) of Etch Profile and Metal Fill for Nano Through-Silicon Via (nTSV) Fabrication	Advanced Packaging	ACCEPT
69	Hongjin Zhang, Jiuzhou Zhao, Zikang Yu, Mingxiang Chen and	Phosphor-converted white LD with high luminous efficacy through sapphire lens based PiGF	Optoelectronics and New Display	ACCEPT
70	Ziyao Luo, Xiuzhen Lu and Zhenhao Chen	Electro-Thermo-Mechanical Analysis of CNTs-Cu-Filled TSV Arrays for Enhanced Reliability	Quality & Reliability	ACCEPT
71	Rui-Zhe Wu, Tzu-Hsing Chiang, Shu-Ting Mai, Chien-Yu Huang, Chen-Chao Wang and Chin-Pin Hung	Synergistic Additive Formulation and Electrochemical Analysis for Copper Grain Refinement in Advanced Semiconductor Packaging	Packaging Materials & Processes	ACCEPT
72	Siyu Chen, Yiqian Huang, Yuhao Cao, Xinyuan Wang, Ruijie Liu and Yun Mou	Thermo-Mechanical Reliability of TGV: Influence of Side wall angle and Copper Thickness	Packaging Design & Modeling	ACCEPT
73	Jiahui Yan, Hongyuan Hong, Bo Li, Faci Cheng and Yuebo Liu	Accelerated Aging and Finite Element Co-Validation Framework for Bonding Interface Reliability in III-V-on-Si Heterogeneously Integrated Lasers	Quality & Reliability	ACCEPT
74	Shuainan Lin, Yanbo Tang, Chang Niu and Boping Wu	A new method to test the value of Rjc-bottom for a BGA chip with T3ster	Quality & Reliability	ACCEPT
75	Wei Wu, Bo Wen Cai, Li-Yin Gao and Zhi-Quan Liu	Investigation of Functional Additives for Cyanide-Free Au-Sn Alloy Electroplating and Its Application in Electronic Packaging	Packaging Materials & Processes	ACCEPT
76	Hao Zhang, Qiao Qiao and Liang Wang	Application of Dual-Side Silver Sintering Technology in 6-Inch IGCT Devices	Interconnection Technologies	ACCEPT
78	Renjie Gu, Wenqi Li and Ming Li	SAFO PACKAGING TECHNOLOGY	Advanced Packaging	ACCEPT

81	Rajan Ambat	Designing Humidity-Resistant Electronic Packaging: Experimental and Modelling Insights	Quality & Reliability	ACCEPT
82	Wenkai Yue, Shixiao Li, Xiaowei Wang, Shan Jia, Yu Sheng and Shaoyu Chen	High-Temperature MCM Technology for 200 °C Power Electronics in Harsh Environment Applications	Power Electronics & Energy Electronics	ACCEPT
83	Wanchun Tian, Xiaofeng Yang, Bingxu Ma, Peijiang Liu, Jingxi Wu and Wen Yang	Research on Thermal Testing Characterization Methods for High-Speed Gallium Nitride Devices	Quality & Reliability	ACCEPT
84	Shiyu Zhang, Huiquan Cao, Zhou Yang, Jiajie Kang, Wei Wang and Chi Zhang	Multi-layout and multi-objective optimization of microchannel heat sinks assisted by surrogate model-based evolution	AI-Enabled Packaging Technologies	ACCEPT
85	Junqi Wang, Yang Yang and Yihang Yao	A Novel 3D Hermetic Stacked Packaging Structure Based on Kovar-Pillar Arrays for Spaceborne Electronics	Emerging Technologies	ACCEPT
86	Ping Wu, Zhen Liu, Yiou Qiu, Linzheng Fu, Wenhui Zhu and Liancheng Wang	Analytical and Numerical Investigation of Warpage in Large-Size Multilayer Organic Substrates	Packaging Design & Modeling	ACCEPT
88	Pan Xu, Zhenzhong Yang, Shuairong Deng, Shun Li, Quanfeng	Design of a TSV-based MEMS Rogowski Coil for Current Measuring in microsystems	Emerging Technologies	ACCEPT
89	Loon Wooi Fook, Yongbo Wang and Jianyong Pan	Cost Effective and Reliable Rework Process for BGA with Head-in-Pillow Defect	Quality & Reliability	ACCEPT
90	Qianwen Xu, S. W. Ricky Lee and Yusong Guo	Rapid and Scalable Fabrication of Coaxial 3D-Printed Interconnects for Multiplexed Microfluidic Systems	Advanced Manufacturing	ACCEPT
91	Xinqing Lei, Gang Dong and Ziyu Zhou	Design of a 3D Compact Bandpass Filter Based on Dual-Layer	Packaging Materials & Processes	ACCEPT
94	Yufei Bai, Erni Shao, Guining Yu, Jia Yang, Yan Ma and Chenxi Wang	Sequential Plasma-activated low-temperature direct Ru-Ru bonding for ultrahigh density interconnection	Interconnection Technologies	ACCEPT
95	Yuhao Cao, Xinyuan Wang, Yiqian Huang, Siyu Chen, Ruijie Liu, Yun Mou and Jianming Xu	Sintering Molecular Dynamic Behaviors of Cu-Ag Nanoparticles with Different Architectures for Power Electronic Interconnection Packaging	Interconnection Technologies	ACCEPT
96	Yupu Ma, Tao Wei, Jiyu Qian, Haojie Huang and Weiqiang Zhang	Investigation of silicon manifold microchannel cooler for RF chip array cooling with heat flux exceeding kW/cm2	RF Electronic Packaging	ACCEPT
97	Xing Xu, Gaiqing Chen and Yong Xiao	Study on the strength and microstructure of the ultrasonic-assisted solder of aluminum alloys	Interconnection Technologies	accept?
98	Junshan Han, Mingyu Yang, Qin Gu, Yipu Zhang, Jiliang Zhang	FNO-Accelerated Thermally Aware Chiplet Placement for 2.5D	AI-Enabled Packaging Technologies	ACCEPT

99	Jiaxuan Zhang, Yingtao Ding, Ziyue Zhang, Yuwen Su, Yigang	Study of Keep-Out Zone (KOZ) Characteristics for Parylene-Liner TSVs Fabricated by Double-Sided Processes	Quality & Reliability	ACCEPT
102	Pengfei Zhang, Sean Xu, Guangming Li, Peter Wei and Xinyu Li	Investigation and improvement of Delamination Failure in LQFP 10×10 Dual-Die Package	Quality & Reliability	ACCEPT
103	Liang Chen and Hu He	Multi-Objective Optimization of Global Warpage and Die–Underfill Peel Stress in Lidless 2.5D Chiplet Packages	Packaging Design & Modeling	ACCEPT
105	Wu Yilong, Xiaomeng Lyu, Zhang Jiaming, Li Yaru, Zhao Mingxiao and Weihua Xu	Mechanism Analysis of DFB Semiconductor Laser Chip Spectral	Quality & Reliability	ACCEPT
108	Huang Yilong	Low Thermal Resistance and High-Strength Interconnection Technology for Power Chips	Interconnection Technologies	reject?
110	Xiaoling He and Chengqiang Cui	Vertically Aligned Carbon Nanotubes on Graphene Sheets for Multifunctional Elastomeric Thermal Interface Materials	Advanced Packaging	ACCEPT
112	Leiming Du, Huaiyu Ye and Guoqi Zhang	Particle Morphology-driven Microstructure and Fracture Toughness in Sintered Copper Particles	Power Electronics & Energy Electronics	ACCEPT
114	Zishan Xiong, Shichen Xie, Yulong Chen, Fuxin Du, Xingchao Mao and Yingxia Liu	Study on the Mechanism of Void-Free Nano-Through Silicon Via(TSV) Filling	Interconnection Technologies	ACCEPT
115	Zhou Zhou, Raul Martinez and Haibo Fan	Robust SiC Package Reliability Study by Simulation	Packaging Design &	ACCEPT
117	Zhiyuan Zhang, Lin Liang, Yizhu Wang, Liuyu Tu and Ke Wang	Research on Sintering Performance Optimization of Large-Area Cu Sintering for Press-Pack IGBT Packaging	Packaging Materials & Processes	ACCEPT
118	Qunxing Li, Peng Su, Jinhui Li, Guoping Zhang and Rong Sun	Synergistic Mechanical Toughness and Thermal Stability of Alkali-Soluble Photosensitive Resin for Solder Resist	Packaging Materials & Processes	ACCEPT
119	Peng Su, Qunxing Li, Jinhui Li, Guoping Zhang, Pengli Zhu and Rong Sun	Performance Enhancement of Solder Resist Using Long-Chain	Packaging Materials & Processes	ACCEPT
121	Su Ding and Yixiang Wang	Effects of Pre-drying on Microstructure and Shear Strength of Low-Pressure Sintered Micron-Ag Joints	Emerging Technologies	ACCEPT
122	Jiahao Wu, Jiayun Li, Kang Li, Qiang Liu, Guoping Zhang and	Single-layer Temporary Bonding Materials Suitable for Mechanical De-bonding in HBM Process	Packaging Materials & Processes	ACCEPT
123	Junbo Zang, Fangcheng Wang and Shuye Zhang	Laser Debonding Process Based on Novel Non-Destructive Release Materials for Advanced Packaging	Advanced Packaging	ACCEPT
124	Hebin Zhang, Zihao Liu, Zeyu Zheng, Yang Liu, Ruoyu Zhang, Huaiyu Shao, Gang Li, Pengli Zhu and Rong Sun	In Situ Research of Internal Stress in Epoxy Composites Stabilized via Negative Thermal Expansion Compensation for Advanced Electronic Packaging	Advanced Packaging	ACCEPT

125	Chong Gao, Ran Cheng, Yao Duan and Yulu Liu	Reliability Assessment and Multi-Stress Lifetime Modeling of 1200 V SiC MOSFETs for Low-Voltage Power Distribution Applications	Power Electronics & Energy Electronics	ACCEPT
126	Lezhi Ye, Lu Li, Bing Zhao, Zhi Tian, Weiming Wang and Guangzhao Yang	Study on Hybrid Force/Position Control Considering Thermal Disturbances in Chip Thermo- Compression Bonding	Advanced Manufacturing	ACCEPT
127	Jian Wang, Bo Yang, Xinmiao Wang, Yuxian Song, Yingying Dou	High-Accuracy Interchangeable Thin-Film NTC Sensors via Heterogeneous Packaging and Wafer-Level Calibration	Emerging Technologies	ACCEPT
129	Yulong Chen, Yingxia Liu, Xingchao Mao, Zishan Xiong and Angmin Li	Signal Transmission Evaluation of Interconnect Networks in a 3D Stacked Computing System	Interconnection Technologies	accept?
130	Yang Fan, Zhao Lei, Zhou Yikun, He Huang and Su Qiang	First-Principles Investigation of Intermetallic Compounds in Cu-Ni-Sn Solder Joints	Packaging Design & Modeling	ACCEPT
131	Han Li, Lei Liu, Yueting Qiao, Jiaqi Liu, Yuting Zhang, Huan Yu and Xingyu Mi	3D Integration Technology of Non-hermetic Packaging Based on Organic Substrate with Open Cavity	Advanced Packaging	ACCEPT
133	Hao Sun, Shijiao Liu, Yabin Sun, Ziyu Liu and Delong Qiu	Thermal Modeling and Topology Optimization of Through-Silicon Via Arrays in 3D Integrated Chips Based on Reduced-Order Methodology	Interconnection Technologies	ACCEPT
134	Jianfang Zhu, Shikang Liu, Dongdong Shao and Kunpeng Ding	Embedded Chip Packaging (ECP) Solution for an Ultra-Compact	Advanced Packaging	ACCEPT
136	Xudong Luo, Dongdong Shao, Kunpeng Ding and Shikang Liu	Optimization of PCT Endurance for High-Voltage VDMOSFETs in	Advanced Packaging	ACCEPT
137	Kaige Liu, Haoyu Zhu, Linlin Mo, Gang Li, Pengli Zhu, Binbin Zhou and Rong Sun	Raman Spectroscopic Elucidation of Stabilizer's Mechanism in Mitigating Thermal Oxidative Aging of Underfill	Packaging Materials & Processes	ACCEPT
138	Yuanyuan Yang, Yehan Zha, Ruoyu Zhang, Futian Zhai, Zihao	Low-CTE Underfill with Monodisperse Mesoporous Silica Nanofillers for 2.5D Packaging	Packaging Materials & Processes	ACCEPT
140	Changming Wu, Guanghong Liu and Yanbo Tang	Signal Integrity Characterization of Ultra-Fine Line RDL Interposer via Design, Simulation and Measurement	Packaging Design & Modeling	ACCEPT
144	Jinglu Peng, Ziliang Pang, Jisen Qiang, Botao Ren, Yichao Han and Junjie Gao	Study on the Heat Transfer Characteristics in proximity fuze based on the ensemble of nitrogen–vacancy centres in diamond	Optoelectronics and New Display	ACCEPT
145	Qiongfang Zhang, Song Xue, Shaoyi Liu, Jingyang Mu, Siyi Chen, Dongchao Diwu and Congsi Wang	Prediction of Homogeneous Thermal and Mechanical Properties for PCB Conductive Layers Using an Attention-Based Deep	Packaging Design & Modeling	ACCEPT

147	Heran Zhao, Shizhao Wang, Min Kang and Mingxiang Chen	Research on the Microcrack sources and Propagation Induction Mechanism of DPC Copper-clad Ceramic Substrates	Quality & Reliability	ACCEPT
148	Yang Yang, Shanjun Ding, Rui Ma, Jingyi Zhao, Zijun Zhong, Meiying Su, Qidong Wang and Liqiang Cao	Study on curing kinetics of a capillary underfill for application processor (AP) based on isothermal and non-isothermal differential scanning calorimetry methods	Packaging Materials & Processes	ACCEPT
149	Yiqian Huang, Siyu Chen, Xinyuan Wang, Yuhao Cao, Ruijie Liu and Yun Mou	Embedded Microchannel Diamond-Copper Manifold Integrated Heterogeneous Heat Sink for Extreme Thermal Management	Power Electronics & Energy Electronics	ACCEPT
150	Yehan Zha, Yuanyuan Yang, Zhennan Liu, Ruoyu Zhang, Gang Li, Pengli Zhu and Rong Sun	The Effect of Adhesion Deterioration and Stress Relaxation of Underfill on Delamination in Electronic Package during High Temperature Aging Process	Quality & Reliability	ACCEPT
151	Xingya Pan, Lingxuan Yan and Yunwen Wu	Electrodeposited Oriented Nanotwined Cu for Low Temperature	Interconnection Technologies	ACCEPT
152	Wentao Hu, Tao Wang, Jinhui Li, Benxia Huang and Rong Sun	Reliability Regulation of Solder Resist Materials for FCBGA via Rigid/Flexible Alkali-Soluble Resin Blending	Packaging Materials & Processes	ACCEPT
154	Xiangchao Wu, Bin Xiao and Rong Sun	Modulation of Dielectric Properties in Barium Titanate/Epoxy Composites Modified with Different Molecular Architectures	Packaging Materials & Processes	ACCEPT
156	Kai Liu, Xiang Rong Cao and Lichun Wang	Study on Thermosonic Flip-Chip Bonding with Gold Bumps for TR Module	Advanced Packaging	ACCEPT
157	Pengsen Wang, Daowei Wu, Ce Mu, Dou Yewei, Zhihui Liu and Shijun He	Research on Wafer-Level Integration Process of Silicon-Based Microchannels for High-Power Chip Heat Dissipation	Advanced Packaging	ACCEPT
158	Qilong Guan, Xuan Li, Tao Yin, Ruiqi Wang, Rui Bai and Chunjin Hang	Mechanism of electron irradiation induced dissolution of the Ag3Sn in SAC305	Quality & Reliability	ACCEPT
161	Dao-Hang Li, Hou-Xing Zhou, Ze-Tian Yu, Yuan Chen and Yunhui Mei	Reliability design method for aluminum wire bonding in silicon carbide power modules based on aluminum/copper composite foil	Quality & Reliability	ACCEPT
162	Linghui Hu, Mengjia Cui, Jianing Li and Qinglei Sun	Investigation of Microstructural Evolution and Bonding Mechanism in Sintering of Nano-Ag Paste on (111)-Oriented Nanotwinned Cu Film	Interconnection Technologies	ACCEPT

163	Xinyu Li, Wenqian Wang, Qi Qiao, Mifeng Liu, Yan Luo, Bin Sun and Kai Chen	Chiplet-SiP Heterogeneous Integration Technology for Miniaturized Beam Steering Microsystems	Advanced Packaging	ACCEPT
164	Nanjiang Yuan, Han Jiang, Lin Chen, Qingqing Sun and Ziyu Liu	Non-CMP Cu/SiO2 Hybrid Bonding Based on Interlocking Structure	Interconnection Technologies	ACCEPT
165	Dongmei Tian, Yong Liu and Kunpeng Ding	A High Heat Dissipation Solution Of GaN RF Chip Based On FOPLP	Advanced Packaging	ACCEPT
169	Liang Cao, Jiayi Tang, Menghan Li, Manqi Dong, Guanghui Xu and Ming Li	Physics-Cascaded Deep Learning for Nonlinear Thermo-mechanical Reliability Assessment of Cu TSV Interconnects	AI-Enabled Packaging Technologies	ACCEPT
170	Qin Gu, Mingyu Yang, Yinbo Chen, Yipu Zhang, Jiliang Zhang	D²-DINO: Difference-Aware Feature Pyramid Networks and Defect Token Priors for High Precision PCB Defect Detection	AI-Enabled Packaging Technologies	ACCEPT
171	Lu Han, Zheng Huang, Tiantian Tan, Gang Wang and Xiaotong	Application of Passive Voltage Contrast Technology in Semiconductor Chip Failure Localization	Quality & Reliability	ACCEPT
172	Shuyan He, Yuxin Wan, Yufeng Jin, Lang Chen and Wei Wang	Efficient Image Feature Extraction Via YOLO Framework for Critical Parameter Extraction from TSV SEM Imagery	AI-Enabled Packaging Technologies	ACCEPT
173	Liang Cao, Manqi Dong, Menghan Li, Dan Xu, Zepei Jiang, Yan	Electrografting of Ultralow-k Films on Si(111) via Sterically Hindered Diazonium Chemistry	Packaging Materials & Processes	ACCEPT
174	Garian Lim, Alexander Hartwig, Simon Seethaler, Oliver Matyssek and Tina Guo	Advanced Adhesive Technology for Silicon Photonic and CPO	Packaging Materials & Processes	ACCEPT
175	Bin Jiang, Donghua Yang, Aifan He, Jun Luo, Hao Pan and Chunhong Zhang	Microstructural evolution and interfacial stability of a novel low-temperature Sn14In3Ag1Zn/Cu solder joints under isothermal aging	Quality & Reliability	ACCEPT
176	Bin Jiang, Donghua Yang, Aifan He, Kailun Hu, Hao Pan and Chunhong Zhang	Interfacial Reactions and Amorphous Layer Formation in Sn25Bi30In5Ag10Zn/Cu High-Entropy Alloy Joint	Packaging Materials & Processes	ACCEPT
177	Shangmo Jiang and Yunlong Li	Simulation and optimization study of bottom-up TSV electroplating process based on multi-physics coupling and additive competitive adsorption	Interconnection Technologies	ACCEPT
178	Liang Cao, Ruiyang Wu, Menghan Li, Jiayi Tang and Ming Li	Multi-Objective Prediction and Discovery of High-Performance Polymer Dielectrics for Advanced	Packaging Materials & Processes	ACCEPT
179	Hyun-Dong Lee, Yeo-Jin Kim, Ha-Bin Song, Eun-Ho Lee, Sung-Ho Park, Won-Seob Cho, Yong-Jin Park, Soichi Watanabe,	Effects of Cu Film Microstructure on Bonding Performance of Cu-to-Cu Bonding: Interface Elimination Driven by Grain Growth Kinetics	Packaging Materials & Processes	ACCEPT

181	Honghai Cao, Yulong Wang, Yilong Ouyang, Zhongxu Zhang, Haitao Ma and Shengzhi Hao	Phase Field Modeling of Electromigration Failure Mechanisms in Sn-Bi Solder Joints Incorporating Electro-Thermo-Mechanical Coupling	Packaging Design & Modeling	ACCEPT
182	Xueping Peng, Xingyan Zhao, Yang Qiu, Shaonan Zheng, Yuan	A Low-loss Optical Glass Bridge (OGB) for Co-packaged Optics (CPO)	Emerging Technologies	ACCEPT
183	Fang Zheng, Zhang Jihua, Kong Xin, Liu Jinxu, Li Borui, Wang Zihan and Zhang Wanli	Design and Optimization of a TGV-Based V-Band Seventh-Order	Packaging Design & Modeling	ACCEPT
184	Kai Xiong, Xingyan Zhao, Yang Qiu, Shaonan Zheng, Yuan Dong, Qize Zhong and Ting Hu	Thermal Reliability of 80Au20Sn Solder Bump for Optoelectronic Heterogeneous Integration	Optoelectronics and New Display	ACCEPT
187	Haojie Zhu, Yile Ye, Yujun Wu, Kuan Deng, Kexin Fu, Yanjun Wan, Rong Sun and Pengli Zhu	Effect of Silicone-Based Toughening Agents on the Mechanical and Thermal Properties of Highly Filled Epoxy Underfill for Advanced Packaging	Packaging Materials & Processes	ACCEPT
188	Pengfei Yue, Zheng Huang and Weiyao Jia	Reliability Analysis of GaN Enhancement-Mode HEMTs After 1000h High Temperature Reverse Bias Stress	Quality & Reliability	ACCEPT
189	Hangbo Shi, Qian Wang, Lai Zhang, Jing Wang and Jian Cai	Physics-Based Simulation and Structural Optimization for Process-Induced Effects in CoWoS Packaging	Packaging Design & Modeling	ACCEPT
190	Shibo Zu, Ziniu Yu, Chuanjia Wang, Kezhong Xu, Weibin Hui and Fulong Zhu	Electromigration-Induced Atomic and Stress Evolution in Copper Strips	Advanced Manufacturing	ACCEPT
191	Kezhong Xu, Weibin Hui, Yuxin Chen, Ziniu Yu, Shibo Zu and Fulong Zhu	Study on the Shear Mechanical Properties and Deformation Mechanisms of Cu/Ta Bilayer with the Tilted Interface	Advanced Manufacturing	ACCEPT
192	Siqi Lan, Ruonan Wu, Haiming Zhu, Yehuan Wang, Renjie Su,	A Ka-Band Dual-Band Coplanar Phased Array System-in-Package	RF Electronic Packaging	ACCEPT
193	Tiansheng Ge, Xu Han, Yiheng Rao and Hao Wang	A Millimeter-Wave Substrate Integrated Waveguide Filter Based on TSV Technology	RF Electronic Packaging	ACCEPT
194	Liang Cao, Menghan Li, Dan Xu, Wenlu Wu, Junhao Hua, Cheng	Discovery of High-Performance Low-k Interconnect Materials via Multi-Target Machine Learning Model	Packaging Materials & Processes	ACCEPT
195	Qiushi Zhang, Hao Guan and Pan Liu	Thermo-Mechanical Stress Analysis and Optimization of TOLL-Packaged SiC MOSFETs Under Second-level Power	Power Electronics & Energy Electronics	ACCEPT
197	坤 舒, 志康 邓, Hongbo Zhan, Xing Zhong, Chuanneng Luo, Fang	3.2T Near-Packaged Optics (NPO) for AI Computing Center Network Interconnects	Advanced Packaging	ACCEPT
198	Liang Cao, Anyang Xiong, Manqi Dong, Zepei Jiang, Yan Zeng,	Thermal Analysis of BEOL Structures: Effects of ILD Thermal Conductivity and Barrier Thickness	Interconnection Technologies	ACCEPT

199	Kai Peng, Fengtao Yang, Zizhen Cheng and Laili Wang	Molecular Dynamics Simulation of Nano - Copper Sintering for Chip Packaging: Effects of Temperature and Pressure on Bonding Quality	Packaging Materials & Processes	ACCEPT
201	Ting Xin, Yujun Wu, Shufang Zhang, Gang Li, Rong Sun and Pengli Zhu	Enhancing Interfacial Adhesion and Thermomechanical Toughness of Epoxy Underfill for Advanced Electronics Packaging	Packaging Materials & Processes	ACCEPT
202	Shaohui Liu, Runlin Zhang, Xiaozhi Liu and Pingan Du	A Novel Multi-Chip Wafer-Level Package with Enhanced Thermal Dissipation and High Isolation	Packaging Design & Modeling	ACCEPT
204	Yidong Tian, Jiajun Zhou, Penghui Guan, Xianli Xie and Huai Zheng	Effect of Residual Stress on the Debonding Behavior of Heterogeneous Thin-Film/Substrate Structures	Quality & Reliability	ACCEPT
205	Li Ma, Yan Wu, Xuelian Han, Min Yao and Fen Chen	Pressure Cu Sintering Paste Developed for Next Generation Interconnection Material	Packaging Materials & Processes	ACCEPT
206	坤 舒, 志康 邓, Bin Pan, Fan Yang, Liangliang Zhang, Yuanfu Wan, Chuanneng Luo, Fang Dong and Sheng Liu	Warpage Optimization for Near-Packaged Optics (NPO) in 3.2T Optical Modules for AI Computing Center Network	Advanced Packaging	ACCEPT
207	Yifan Ma, Lang Chen, Jianyu Du, Wei Wang, Chi Zhang and Pan	Sub-Micro Wiring Method for Embedded Silicon Fan-Out on Reconstructed Wafer Surface	Advanced Packaging	ACCEPT
208	Shufang Zhang, Ting Xin, Yunfan Yin, Mingqiang Liu, Jie Pang, Kang Zhang and Pengli Zhu	Enhancing Hygrothermal Aging Resistance and Interfacial Adhesion of Liquid Molding Compound/Silicon Systems via Chemical Modification	Packaging Materials & Processes	ACCEPT
209	Jingjing Feng, Mingsheng Ma, Feng Liu, Wangjia Han and Zhifu Liu	Thick-Film Silver Electrode and Optimization of Its Soldering Characteristics for Wiring of Multilayer Ceramic Packaging Substrate	Packaging Materials & Processes	ACCEPT
211	Liang Cao, Linkang Lu, Jiayi Tang, Guanghui Xu and Ming Li	Predicting Structure-Dependent Dielectric Responses in High-k Oxides using Physics-Informed Graph Neural	Advanced Manufacturing	accept?
212	Luo Guohu, Zhao Yishi and Yongxiang Hu	Metal micro-bump arrays printing via laser-induced metal microdroplets deposition	Interconnection Technologies	ACCEPT
213	Matthias Fettke, Anne Fisch, Alexander Frick, Anatoli Kondrat and Thorsten Teutsch	Minimized intermetallic compound formation at Cu-Pillar bond interfaces through dual laser assited reflow technology	Advanced Packaging	ACCEPT
214	维红 刘, 凤燕 田 and 嘉成 魏	GA-Based High-Precision BPNN Surrogate Model for W-Band LCP	RF Electronic Packaging	ACCEPT

216	Mengfei Xu, Carlos Wang, Jesus Wang, Cuicui Xiao, Jason Wang, Ken Qian and Howie Li	Research on Standard Test Structures and Key Factors for Bumping Resistance in Advanced Packaging	Quality & Reliability	ACCEPT
218	Rijun Mao, Yuexing Wang, Linwei Cao, Bofeng Li, Yang Tang,	Process simulation and optimization of a heterogeneous WLP structure	Packaging Materials & Processes	ACCEPT
219	Yaoting Wang, Huai Zheng and Yiying Zhu	Mechanistic Insights into Dielectric Interface Reconstruction under Different Surface Activation Conditions for Hybrid Bonding	Interconnection Technologies	accept?
220	Shaoyu Ma, Juan Tao, Ziyu Liu, Yinan Li, Lin Chen, Qingqing Sun and Yabin Sun	Simulation Study on the Laser Heating Mechanism of Laser-Assisted Bonding Based on the Beer-Lambert Absorption	Packaging Design & Modeling	ACCEPT
221	Yi Mingming, Xiong Jia, Wu Shiqiang, Wang Liancheng, Cao Jiaqi and Wang Ji	Investigation and Mitigation of Blind Via Failures in Advanced Packaging Substrates	Quality & Reliability	ACCEPT
222	Masahiro Saito, Tomohiro Sakata, Tetsuro Ota, Jumpei Yahiro	A Novel Interface Characterization Technique for Hybrid Bonding Process Optimization	Advanced Packaging	ACCEPT
225	Zhengxing Li and Jinfeng Li	Switching Loss Characterisation of 21-Level Inverter in Cascaded H-Bridge Topology for Space Power Electronics	Power Electronics & Energy Electronics	ACCEPT
226	Zhi Wang, Haoran Ma, Hongwei Liang and Kexiong Zhang	Controlled synthesis of Cu@Ag core–shell nanoparticles and the effect of size on silver shell growth mechanism	Power Electronics & Energy Electronics	ACCEPT
227	Jie Wang, Zhou Gui, Tianhao Guo, Haoran Ma and Hongwei Liang	Thermo-Mechanical Lifetime Prediction of Copper Interconnect Joints Based on Finite Element and Machine Learning Fusion	AI-Enabled Packaging Technologies	ACCEPT
228	Wenpeng Jiang, Dongxian Yin, Zibo Yu, Yuzhi Ouyang and Siliang He	Rapid Low-Temperature Sintering of Cu Microparticles with PEG via a Pre-Drying Process	Interconnection Technologies	ACCEPT
229	Wei Dong and Haoyang Liu	Study on Microstructure evolution and Properties for Direct Deposition of SAC305 Bumps by Pulsed Orifice Ejection	Interconnection Technologies	ACCEPT
230	Zhennan Liu, Yunfan Yin, Yehan Zha, Xuecheng Yu, Mingqiang	Synthesis of Bio-based Accelerator and Its Performance Study for Epoxy Molding Compound	Packaging Materials & Processes	ACCEPT
233	Xu Long, Percy M. Iyela, Hongbin Shi, Yanpei Wu, Lianfeng Ren and Cheng Zhou	Connectivity and thermal transport in porous sintered silver: A statistically controlled 2D–3D comparison	Packaging Design & Modeling	ACCEPT
235	Yujun Wu, Yile Ye, Kuan Deng, Haojie Zhu, Siyuan Liao, Yanjun Wan, Pengli Zhu and Rong Sun	High Thermally Conductive and Low Viscosity Epoxy Composites for High Bandwidth Memory 3D Packaging	Packaging Materials & Processes	ACCEPT

236	Zhishen Liao, Hui Tang, Yue Deng, Xiangpeng Li and Duoyu Lu	Research on a Parasitic Error Self-Compensating ZTT Nano-Alignment Device for Advanced Packaging	Advanced Packaging	ACCEPT
237	Liang Peng, Yuanyuan Yang, Kexin Fu, Long Li, Yan Pan, Gang Li and Pengli Zhu	Cure shrinkage stress measurement of underfill and stress evolution in flip chip package during underfill curing process.	Quality & Reliability	ACCEPT
238	Haoyu Wu, Wenbo Luo, Yu Sun, Yufeng Li, Linyi Du and Mengjie Ji	A System Level Hyper-Skip Impedance Matching Method for High-speed Interconnect of Heterogeneous Chiplet	Packaging Design & Modeling	ACCEPT
240	Yile Ye, Yujun Wu, Kuan Deng, Haojie Zhu, Pengli Zhu, Rong Sun, Yanjun Wan and Siyuan Liao	Enhancing the Epoxy/Copper Interfacial Shear Strength via Additive Modification for 3D Advanced Packaging	Packaging Materials & Processes	ACCEPT
241	Mingxi Tu, Pengshou Cheng, Feng Li, Huai Zheng and Yiying Zhu	Automated Thermo-Mechanical-Optical Co-Simulation for High-Density Optical Modules: Analysis of Thermally Induced Misalignment and Coupling Loss	Optoelectronics and New Display	ACCEPT
242	Hanwen Feng, Yanhong Tian, Taohan Wang, Wan Tai and Jiayun	A Physics-Guided Neural Network for Board-Level Key Thermal	AI-Enabled Packaging Technologies	ACCEPT
244	Zhang Jingran, Liang Yuxin, Wang Yiwei, Li Jingdong, Li Wenlong and Yang Daoguo	Warpage Analysis of Embedded Power Modules Based on Thermal-Mechanical Coupling	Quality & Reliability	ACCEPT
245	Jing Chen, Yuanyuan Yang, Jinbao Yang, Gang Li, Ting Xin, Pengli Zhu and Rong Sun	Effect of Underfill Properties on Flip-Chip Reliability in No-Clean Processes	Quality & Reliability	ACCEPT
246	Kuan Deng, Zeyu Zheng, Yujun Wu, Yile Ye, Pengli Zhu, Rong Sun, Yan-Jun Wan and Siyuan Liao	Electrically Insulating yet EMI-Shielding Epoxy Composites Enabled by Organic–Inorganic Hybrid-Coated Magnetic Fillers	Packaging Materials & Processes	ACCEPT
247	Jun Huang, Rui Gao, Lei Sun, Guannan Yang, Chengqiang Cui, Yu Zhang and Chao Li	Effect of Via Pitch on the Thermal Reliability of Through Glass Via under the Stress of High-Temperature Storage with 300℃	Advanced Manufacturing	ACCEPT
248	Tiantian Shao, Huan Yu, Ding Zhang and Chao Wang	Thermal Characteristic Optimization of a Novel Embedded Heat Dissipation Structure in 3D PoP Packaging	Packaging Design & Modeling	ACCEPT
249	Jianming Fang, Chengwei Zhang and Zihao Liu	Failure Mechanisms of Silver Bonding Wire in Microelectronics Packaging	Quality & Reliability	ACCEPT
250	Jinfeng Chen, Xu Sun, Zhenyang Lei and Huai Zheng	Image-Recognition-Based Micro-Region Equivalent Thermal Modeling of PCB	Packaging Design & Modeling	ACCEPT

251	Yunfan Yin, Zhennan Liu, Shufang Zhang, Xuecheng Yu, Rong Sun, Gang Li and Pengli Zhu	Tailoring LMC/UF Interfacial Reliability: Warpage Control and Adhesion Enhancement via Modified Liquid Molding Compounds	Packaging Materials & Processes	ACCEPT
252	Jianming Fang, Jinzhou Li and Xinbin Guan	Failure Analysis of Bond Pad Cratering in Gold, Copper, and Silver Wire Bonding	Quality & Reliability	ACCEPT
253	Xiaoyang Ran, Qian Lu, Wenhan Chang, Jian Zhang, Xiaomao	Study on the Microscopic Mechanism of Au-Pd Alloy Bumps Improving the Reliability of Thermosonic Flip Chip Bonding	Advanced Packaging	ACCEPT
255	Yinfeng Yang, Juan Ma and Lu Liu	Viscoelastic Equivalent Modeling and Simulation for Warpage Evolution and Correction in Fan-Out Wafer-Level Packaging	Packaging Design & Modeling	ACCEPT
257	Zhizhe Wang, Yusheng Li, Jun Luo and Yuhai Chen	Research on High-Temperature Reliability of Automotive-Grade Intelligent Power Switch Chips	Quality & Reliability	ACCEPT
258	Tiantian Tan, Yao Chen, Lu Han, Xiaodong Wang, Zhimeng Yang, Zheng Huang and Xiaotong Guo	Simulation Analysis on Reliability of Voltage Reference Chip Under Thermal Cycle Loads	Quality & Reliability	ACCEPT
260	Yizhen Hu, Kelaiti Xiao, Siqi Zhang and Yuechen Zhuang	Low-Temperature BCB Bonding for Piezoelectric-resistive Coupled Sensor Packaging	Packaging Materials & Processes	ACCEPT
261	Tao He, Bin Xie, Zhoulong Xu, Zhouping Yin and Hao Wu	Revealing the Effects of Particle Size and Distribution on the C2W Hybrid Bonding Dynamics	Packaging Materials & Processes	ACCEPT
262	Dandan Su, Qihao Liu, Yongwang Zhou, Xinming Li, Yihua Fu and Ji Zhong	QoS Guarantees and Isolation for Multi-tenant SSDs in Cloud Environments	Quality & Reliability	ACCEPT
263	Menghua Wang, Dan Yang, Liyi He, Xiao He, Na Mei and Keqing	Impact of High Frequency on HK/MG Off-state TDDB Reliability	Quality & Reliability	ACCEPT
264	Jiaying Wang, Kai Zheng, Chaojun Ming, Jiabing Yu and Xianping Chen	PerformanceTermination-Dependent Interfacial Stability in β-Ga2O3/Diamond Heterostructures	Power Electronics & Energy Electronics	ACCEPT
268	Ran Lu, Xin Tang, Yongjie Ding and Mingxiang Chen	Tetrapod-like zinc oxide whisker modified inorganic packaging adhesive with better moisture and high temperature resistance	Packaging Materials & Processes	ACCEPT
269	Yinzuo Qian, Shiwei Zhu, Yuyang Zhan, Shuanshe Chao, Shaobing Lin, Dan Yang and Na Mei	IDDQ Degradation Failure Analysis During HTOL Test and SOA	Quality & Reliability	ACCEPT
271	Jintong Ai, Zhi Jiang, Ruoxuan Zhang, Sichen Ge, Rui Yang, Xuanxiang Wang and Minkai Luo	Highly Robust Stretchable Conductors Enabled by Substrate-Heating-Assisted PVD	Advanced Manufacturing	ACCEPT

272	Shuchao Bao, Ningning Xu, Yi Zhong and Daquan Yu	High-Density Heterogeneous Integration of Collective Si Dies and Glass wafers via Low-Temperature Die-to-Wafer Bonding	Emerging Technologies	ACCEPT
276	亚鹏 宋, 慧珺 操, 恒辉 王, 田德 王, 依灿 郭, 昊 薛 and 志昊 张	Self-Healing and Radiative-Cooling E-Skin for Advanced Thermal Management and Reliable Encapsulation	Emerging Technologies	ACCEPT
278	Kaixiang Mao, Jiexun Yu, Qian Wang, Yongbo Wu and Jian Cai	Indium-capped Copper Pillar Flip-chip Scheme Compatible for 2.5D Superconducting Quantum Computing Architecture	Emerging Technologies	ACCEPT
279	Wen Peng, Wei Zhao, Bo Zheng and Kemu Li	Study on Stress Degradation Mechanism and Reliability of Typical TSV Process Defects Based on Simulation-Experiment	Packaging Materials & Processes	ACCEPT
280	Junyu Ye, Qicun Lou, Jingzhe Liu, Ziyu Liu, Lin Chen, Qingqing Sun and Yabin Sun	Polyimide-Based Low-Temperature Heterogeneous Bonding for	Interconnection Technologies	ACCEPT
282	Jianyu Du, Jiale Tu, Haoyang Sun, Shangyang Shi, Feng Ji, Jiajie Kang, Chi Zhang and Wei Wang	Chip-level Silicon Vapor Chamber with MEMS Micropillar Wick	Advanced Manufacturing	ACCEPT
283	Ting Yong, Huizhong Zeng, Guosheng Yan, Fengxia Shen, Yushi	Anisotropic Tensor Mapping for Accurate Warpage Prediction of HDI Substrates under Aggressive Mesh Scaling	Packaging Design & Modeling	ACCEPT
284	Guanqiang Song, Yuhong Li, Jing Jiang, Jianhui Liu and Jian Song	Stress simulation study on Panel level fanout packaging of Multi-MOS modules	Quality & Reliability	ACCEPT
285	Yifan Huang, Zixian Song, Lei Nie, Peicheng Chen, Guanglan Liao and Tielin Shi	Study on the Failure Mechanism of Vertical Interconnect Structures Based on the Atomic Flux Divergence Method	Interconnection Technologies	reject?
286	Hui Zeng, Qiaobo Dai, Lei Liu, Boyu Zheng, Peng Zhao, Zhen Liu, Lanying Xu and Wenjuan Guo	A Study on Optimization of Mold-flow Balance for SiP Packages	Packaging Materials & Processes	ACCEPT
287	Jianhui Liu, Yuhong Li, Guanqiang Song, Yi Tan, Jian Song and Jing Jiang	Design and Optimization of Interface Reliability for GaN Power Device Packages Based on FOPLP	Quality & Reliability	ACCEPT
288	Muying Yu, Jiayun Feng, Shang Wang, Baolei Liu, Pengrong Lin, Shimeng Xu, Hengtong Guo and Yanhong Tian	Generalized life prediction modeling for electrical-magnetic-thermal-force multi-physical field coupling of PCB assemblies	Quality & Reliability	ACCEPT
289	Tian Lan, Wei Fu and Jun Wang	An Analytical Model for Multi-Layer FOPLP Warpage Prediction with Thermo-Gravity Coupling Effect	Packaging Design & Modeling	ACCEPT
290	Han Wu, Guanping Yang, Kaizhan Wang, Hao Tong and Xiangshui	A 3ω-Based Method for Thermal Interface Resistance Measurement and Degradation Mechanisms of Ti/SiO2	Advanced Packaging	ACCEPT

291	Han Wu, Yang Zhou, Yunxiang Jia, Hao Tong and Xiangshui Miao	Thermal Conductivity Characterization of Nano-Interconnects for Hot Spot Mitigation in Advanced Packaging	Advanced Packaging	ACCEPT
292	Kazuki Yorita, Akihiro Orie and Shinya Shimizu	Die attach / Via filling Cu-Nano Sintering Paste using Self- Assembling Mechanism	Power Electronics & Energy Electronics	ACCEPT
293	Weijian Zhang, Jinsong Fang, Lingshuang Hu, Li Zeng, Yong Zhang and Yan Zhang	Experimental Investigation on Thermosensitive Properties of Laser-Induced Graphene on Flexible Substrate	Packaging Materials & Processes	ACCEPT
294	Jing He, Yangming Liu, Fei Chong Ng, Bo Yang and Ning Ye	Stress Analysis and Optimization of Thin ASIC Die Pick Up Process	Packaging Design & Modeling	ACCEPT
297	Yanli Wang, Zhengbin Huo, Ling Li and Qing Cao	Multi-scale Failure Analysis of 3D Stacked Package with RDL Metal Residue and Micro-bump Cracking	Quality & Reliability	ACCEPT
298	Chenru Zhang, Bin Xie, Zhoulong Xu, Zhouping Yin and Hao Wu	Effect of Surface Hydroxyl Density on Room-Temperature Pre-Bonding of SiO_2 : A Molecular Dynamics Study	Advanced Packaging	ACCEPT
299	Huacheng Fu, Mingqi Lei, Lu Liu and Zhikuang Cai	Identification of Constitutive Parameters of Porous Sintered Silver Nanocrystals Based on Machine Learning and Differential Evolution	Packaging Design & Modeling	ACCEPT
300	Ti Chen, Kiyotaka Kanno, Takeshi Tokuyama, Yosuke Yasuda, Ichiro Shimoda, Naoya Suto, Masao Watanabe, Takahiro	Minimizing TIM Thickness and Coolant Bypass in Double-Sided Cooled Automotive Power Modules via an Adaptive Split-Fin	Power Electronics & Energy Electronics	ACCEPT
301	Taohan Wang, Hanwen Feng, Wan Tai, Jiayun Feng, Shang Wang,	Knowledge-Informed Learning for Intermetallic Compound Thickness Prediction and Optimization in Reflow Soldering	AI-Enabled Packaging Technologies	ACCEPT
302	Cong Yue, Kun Zhang, Jiajia Deng, Meng Li and Min Yao	Investigation of high conductive Pressure-less copper sintering for SiC Power Package Bottleneck solution	Power Electronics & Energy Electronics	ACCEPT
303	Xun Zhang, Bin Xie, Zhoulong Xu, Zhouping Yin and Hao Wu	Research on Heat Conduction Enhancement Methods for Local	Advanced Packaging	ACCEPT
304	Ziyang Lu, Tianxiao Bao, Shaoxing Qu and Guodong Nian	Machine learning-enabled constrained multi-objective design of Chip Packaging Material	Packaging Materials & Processes	ACCEPT
306	Wenkai Lu, Zhoulong Xu, Zhouping Yin, Bin Xie and Hao Wu	Revealing the Dynamics of Vortex-based Contactless Chip Pick-up via Fluid-Structure Coupled Analysis	Advanced Packaging	ACCEPT
307	Zikang Yu, Yang Peng and Mingxiang Chen	Synergetic enhancement of opto-thermal performance for white laser diode by MgO-in-glass layer	Optoelectronics and New Display	ACCEPT
308	Junjie Xiao, Bin Xie, Zhoulong Xu, Zhouping Yin and Hao Wu	3D Printing of Tunable Porous Nano-metal Composite Paste for Wafer Channel filling	Packaging Materials & Processes	ACCEPT

309	Hongqin Wang and Xiaojuan Li	Study on the Influence of Different Censored Data Processing Methods on Solder Joint Thermal Fatigue Life Prediction Results	Quality & Reliability	ACCEPT
311	Enze Xue, Runze Dai and Yonglin Yu	Correlation between RIN and Degradation of DFB lasers	Quality & Reliability	ACCEPT
312	Weida Lin, Ziyuan Shao, Changming Song, Jian Cai and Qian Wang	Signal Integrity Simulation and Design of Differential High-Speed Serial Links in 2.5D Reconstituted Interposer Packaging for Vertical Interconnect	Interconnection Technologies	ACCEPT
314	Haoze Yang, Jiajun Zhou, Penghui Guan, Xianli Xie, Huai Zheng and Junhui Li	Optimization of Thermal Uniformity in a Magnetron Sputtering Heating System via Calibrated Numerical Simulation and Structural Redesign	Advanced Manufacturing	ACCEPT
315	Jiahua Cheng, Wei Zhou, Qinghua Zheng, Jingming Fei and Fu	Size-Dependent Sintering Behavior of Cu Nanoparticles: A Molecular Dynamics Simulation	Packaging Design & Modeling	ACCEPT
316	Zhonghua Yang, Yuchi Yang, Yu Sun, Zhongxun Li, Qingji Zhao, Sijie Yang, Yufeng Li, Wenbo Luo and Wanli Zhang	Mechanical Reliability Analysis of Ultra-Large of Glass-Cavity Embedded EMIB-based Chiplet Packaging	Advanced Packaging	ACCEPT
317	Jane Li, Wei Wang, Xu Wang, Muhammad Faizul Yunus, Pradeep Rai, Donghua Wu, Fen Yu, Jd Loeh, Derek Mong, Baozhu	Hybrid Qualification in Virtual Factory: A Data-Driven Framework for Cross-Site Manufacturing Consistency	Advanced Manufacturing	ACCEPT
318	Ziyuan Shao, Weida Lin, Yang Hu, Jian Cai and Qian Wang	Mold Flow and Thermo-Mechanical Analysis of Through Mold Via (TMV) in Silicon Bridge Packaging	Packaging Design & Modeling	ACCEPT
319	Qishu Bai, Wei Zhou, Zhidong Xia, Qinghua Zheng, Hexiong Qi	Electromigration investigation of Sn40Pb C4 Bumps under High-Temperature and High-Current-Density	Quality & Reliability	ACCEPT
320	Linyi Du, Wenbo Luo, Yu Sun, Yufeng Li, Haoyu Wu and Mengjie Ji	Physics-Informed Multi-Objective Layout Optimization for Power Integrity in High-Density 2.5D/3D Packaging	Packaging Design & Modeling	ACCEPT
321	Chan Liu, Quan Cao, Xuejiao Wang, Tianci Huang, Bolan Liu, Luluzi Lu, Dechen Li, Guidong Deng, Zheng Hou and Lin Zhou	Research on the Soldering Process of High-Bandwidth Flexible Printed Circuit in High-Speed Optoelectronic Devices	Optoelectronics and New Display	ACCEPT
322	Yuxin Liang, Zhuangchao Zhan, Wenlong Li, Jingdong Li, Yiwei Wang, Jingran Zhang and Daoguo Yang	Crosstalk Analysis and Mitigation between Single-Ended and Differential Signals in Silicon Interposers for HBM3 Applications	Interconnection Technologies	accept?
323	Jingdong Li, Yiwei Wang, Wenglong Li, Yuxin Liang, Jingran Zhang and Daoguo Yang	Interpretable Surrogate Modeling and Multi-Objective Optimization of High-Speed GSG Tapered TSVs	AI-Enabled Packaging Technologies	ACCEPT

324	Tingting Zhao, Zhifei Wang, Gangli Yang, Liu Chang and Liyi Li	Enabling Die-to-Wafer (D2W) Hybrid Bonding via Laser Stealth Dicing Technology	Advanced Packaging	ACCEPT
325	Guan'Mei Liu, Shiqi Liu, Bo Yi, Wenbo Luo and Wanli Zhang	AI-Assisted Design of a Dual-Polarized Slot-Coupled Microstrip Antenna Using ANN and PSO Optimization	RF Electronic Packaging	ACCEPT
326	Hanwen Cui, Yanze Gao, Xiaoyue Ding, Zhaotian Li, Xiaofeng	Warpage Bifurcation Behavior of SiC and Si Interposer Wafers: A Thermo-Mechanical Analysis via RVE Modeling	Advanced Manufacturing	ACCEPT
327	Wang Shujun, Sun Yuxin, Feng Jiayun, Wen Jiayue, Qi Meng and Tian Yanhong	Self-powered flexible humidity sensor based on graphene films constructed by metal reduction	Emerging Technologies	ACCEPT
328	Yongbo Wu, Changming Song, Chuan Chen, Jiexun Yu, Yikang	Manifold Integrated Cold Plate for High Power Computing Applications	Emerging Technologies	ACCEPT
329	Tianshun Xiong, Yubo Luo and Junyou Yang	Anisotropic constituents co-reinforced AlN fiber-based composite substrate with high flexural strength and thermal conductivity	Packaging Materials & Processes	ACCEPT
330	Dongjie Liu, Yubo Luo and Junyou Yang	An Active Temperature Control System Based on Thermoelectric Cooling for Improving the Thermal Management	Power Electronics & Energy Electronics	ACCEPT
333	Angmin Li, Yingxia Liu, Xingchao Mao and Yongmao Yang	The Study on interfacial reaction of SnBiIn low melting point solder on various substrates	Interconnection Technologies	ACCEPT
334	Yuxi Jia, Yiru Zhang, Hao Zheng and Guoxiang Miao	AI-based Prediction of Partitioned Equivalent Material Properties of Wiring Structure and Application to PCB Warpage Simulation	Quality & Reliability	ACCEPT
335	Yanyu Hui, Ruisi Xing, Hongbo Qin, Jian Huang and Jingjie Yuan	Fatigue Life of Sn37Pb under Coupled Electro-Thermal-Mechanical Loading	Packaging Design & Modeling	ACCEPT
336	Hao Zheng, Zhiyan Zhao and Yuxi Jia	High-accuracy and High-efficiency Thermal Modeling of Complex Wiring Structures Using Orientation-aware Monoclinic Homogenization Method	Packaging Design & Modeling	ACCEPT
339	Xingchao Mao, Ziting Ye, Yulong Chen, Zishan Xiong and Yingxia Liu	Low-temperature reflow and aging behavior of SnBiIn microbump on 10 μm Ni/Cu pad	Packaging Materials & Processes	ACCEPT
340	Tao Wang, Wei Zheng, Jinhui Li and Rong Sun	Solubility-Driven Phase Morphology Modulation for Tailoring the Dielectric Properties of Polyimide/Soldier Resist Composites	Packaging Materials & Processes	ACCEPT

341	Tang Daokuan, Zhou Zhukun, Wu Fa, Mao Yahui and Zhu Yiying	Study on the Recovery Behavior of Electromigration Voids in Cu Interconnects under Current Reversal	Advanced Packaging	ACCEPT
343	Yan Zhou, Jiani Zhou, Yiqing Xu, Lun Yu, Zhaoqiang Zhang and Jun Wang	Effect of Surface Topography on Interfacial Reliability in Al Wire Bonding of SiC Power Chips	Packaging Design & Modeling	ACCEPT
344	Chenyang Zhou, Heran Zhao, Liying Li, Shizhao Wang, Hongjun Li and Min Kang	An Experimental Study on Non-Invasive Flexible Electronic Sensing Technology for Mimosa Pudica Action Potential Detection	Emerging Technologies	ACCEPT
345	李 靖楷, 窦 宇航, 黄 明宇 and 杨 扬	Evaluation Method for SAW Filter Design Deviations Based on	RF Electronic Packaging	ACCEPT
346	Li Hongpeng	Adaptive Model Order Selection and Physics-Constrained Modeling for Distributed Parameter Extraction of Heterogeneous Interconnects	Packaging Design & Modeling	ACCEPT
348	You Li, Yubo Luo and Junyou Yang	Novel packaging epoxy resin with tunable thermal expansion coefficient and thermal conductivity designed for power devices	Packaging Materials & Processes	ACCEPT
349	Yiwei Wang, Jingran Zhang, Jingdong Li, Wenlong Li, Yuxin Liang and Daoguo Yang	Analysis of the Dynamic Switching Characteristics of GaN HEMTs Considering Parasitic Parameters	Quality & Reliability	ACCEPT
350	Guofu Chen, Fei Yang, Zengqi Xie, Wenguang Zhou, Wuhua Li and Guoliang Zhao	Thermal simulation research on high-voltage and high-power IGBT devices based on high thermal conductivity aluminum diamond material	Packaging Design & Modeling	ACCEPT
351	Yifu Ma, Junyao Ding, Kai Sun, Huasong Gou, Lianmei Wu, Manman Yi and Qiang Zhang	Microstructure and Properties of Carbon/Cu Composites for Thermal Management Applications	Packaging Materials & Processes	ACCEPT
353	Zhengwei Fan, Liyi Long, Siyuan Lv, Xinyan Li, Qidong Xie and Qiyuan Wang	TSV Virtual Microstructure Construction and Failure Simulation Based on GAN and Crystal Plasticity Finite Element Method	Quality & Reliability	ACCEPT
354	Xing Hu, Chongyi Chen, Tingting Sun, Zhen Chen, Shujuan Liu, Tianjian Liu, Jianing Liang and Xiaomin Cheng	Dynamic Evolution of Package Warpage in Die-to-Wafer Hybrid	Advanced Packaging	ACCEPT
356	Wenting Liang, Jianming Zhong, Chongyi Chen, Chen Zhihao, Haoyang Peng, Jie Wu, Xing Hu, Shujuan Liu and Dong Xie	High-Density 3D Multi-Layer Via Capacitors Based on Silicon Oxide Dielectric with Ultra-Low Parasitic Parameters for Advanced ICs	Advanced Packaging	ACCEPT

357	Wentao Wang, Xialei Lv and Jinhui Li	Enhancing SR–Copper Interfacial Adhesion Under Wet-Thermal Conditions: A Facile Physical Blending Approach for	Packaging Materials & Processes	ACCEPT
358	Genwang Wang, Baocheng Wang, Ruoxin Niu, Ce Mu, Xuan Zhang,	High-Density Hole-Array TiN–HfO2–TiN Three-Dimensional Capacitor with Organic Filling	Advanced Packaging	ACCEPT
359	Xing Hu, Chongyi Chen, Tingting Sun, Zhen Chen, Shujuan Liu, Tianjian Liu, Jianing Liang and Xiaomin Cheng	Dynamic Evolution of Package Warpage in Die-to-Wafer Hybrid	Advanced Manufacturing	ACCEPT
360	Penghui Li, Xin Wang, Wanjun Li, Xiaotong Guo and Zhiwei Fu	Study on Failure Mechanism of Through-Silicon Vias Interconnection Under High-Temperature Storage	Quality & Reliability	ACCEPT
362	Songxuan Liu, Yu Sun, Wenbo Luo and Yufeng Li	Investigation on Passive Alignment of EML/DFB With Beam Shaping Lens and Flip-Chip Bonding	Optoelectronics and New Display	ACCEPT
364	Yu Xiao, Dongjing Liu and Yizhe Zhang	Research on Thermo-mechanical Reliability of IGBT Modules Based on Mortise-and-tenon Structure	Power Electronics & Energy Electronics	ACCEPT
365	Shujuan Liu, Xing Hu, Haoyang Peng, Jianing Liang, Wenting Liang, Chongyi Chen, Yiqun Wang and Tianjian Liu	Evaluation of θ-TaN as a High-Performance Thermal Management Material via First-Principles Calculations and Multiphysics Simulation	Advanced Packaging	ACCEPT
366	Guoxiang Miao, Yong Jiang, Hao Zheng, Zhiyan Zhao and Yuxi	Research on Warpage Evolution Mechanism and Key Influencing	Advanced Manufacturing	ACCEPT
367	Jian Huang, Jianning Liang, Chongyi Chen, Renzhi Shao, Yongqiang Feng, Haoyang Peng, Shujuan Liu, Tianjian Liu, Dong Xie and Yiqun Wang	Atomistic-scale surface activation process of SiCN dielectric bonding for hybrid bonding: a molecular dynamics study	Advanced Manufacturing	ACCEPT
369	Mengjie Ji, Wenbo Luo, Yu Sun, Yufeng Li, Haoyu Wu, Linyi Du and Wanli Zhang	Warpage Prediction of 2.5D Packaging Based on Physics-Aware	Packaging Design & Modeling	ACCEPT
370	Xiaole Kuang, Dongjing Liu and Yu Xiao	Analysis of Random Vibration Response and Parameter Optimization of Mortise-and-tenon IGBT Modules Based on Orthogonal Experiment	Packaging Design & Modeling	ACCEPT
372	Tianjian Liu, Haoyang Peng, Shujuan Liu, Chencheng Hu, Zhandi Yang, Xing Hu, Yiqun Wang and Sheng Liu	Screening of Passivation Layer Materials for Low-Temperature Cu-Cu Hybrid Bonding via High-Throughput	Interconnection Technologies	ACCEPT
373	Qingji Zhao, Yu Sun, Yanshuai Chen, Yufeng Li, Jiaming Li, Jing Wu, Zhonghua Yang, Sijie Yang, Wenbo Luo and Wanli Zhang	Design of a Field-Replaceable Hermetic VCSEL Optical Engine for High-Reliability CPO Interconnects	Optoelectronics and New Display	ACCEPT

374	Wenxi Kuang, Dingkun Tian, Mingjie Zhou, Yadong Xu, Yougen	Reversible Adhesion Electromagnetic Shielding Film for PCBA	Packaging Materials & Processes	ACCEPT
375	Tianjun Zhang, Pei Chen and Fei Qin	Simulation of Laser-Textured Microstructure-Assisted Grinding of Silicon Carbide	Quality & Reliability	ACCEPT
376	Yaya Liang, Xintong Liu, Xiaokang Li, Cong Liu and Pingan du	Multi-Field Coupled Simulation for Interposer in 2.5D Packaging Considering Field-to-Field Mapping Errors	Quality & Reliability	ACCEPT
377	Mingjie Zhou, Wenxi Kuang, Dingkun Tian, Yadong Xu, Yougen	Multilayer Structured Thermally Peelable Electromagnetic Shielding Film for PCBA-Level Conformal Shielding	Packaging Materials & Processes	ACCEPT
380	Weixi Zhang, Can Sheng, Wenhan Chang, Yangyang Li, Qingmin	Construction method of ultrasonic thermocompression bonding	Packaging Design & Modeling	ACCEPT
382	Jiasheng Liu, Qi Cao, Haoran Ma, Jiawei Liu, He Yu, Yiyang Cai, Xushuo Zhang, Zeen Ren and Hongwei Liang	A New Method for Preparing Low-Temperature Copper Paste via	Power Electronics & Energy Electronics	ACCEPT
383	Xingyu Li, Siliang He, Lin Li and Yilun Yang	Wetting Behavior of SAC305 Solder on Cu and IMC-Coated Substrates in Formic Acid Atmosphere	Packaging Materials & Processes	ACCEPT
384	Qingqing Xie, Jiang Liu, Henan Song, Huan Liu, Chengwei Hou, Kang Zhang and Jianwei Wu	Full-Wafer Overlay Error Analysis under Anisotropic Effect Based on Local Bonding Simulation in Wafer-to-Wafer (W2W) Hybrid Bonding	Advanced Manufacturing	ACCEPT
386	Xiao Zhang, Xiangqi Qiu, Jiahua Li and Song Wei	Thermal Stress Simulation and Reliability Research of GaN Power Modules Based on InSnBi Solder Flexible Interconnection	Packaging Design & Modeling	ACCEPT
388	Jiangtao Chen and Zhentao Yang	Research on High Reliability of Aerospace-Grade CQFP Ceramic Packaged Devices	Quality & Reliability	ACCEPT
389	Kechen Zhao, Donglin Cao, Peng Sun, Xuzhou Jia, Bing Dai and Jiaqi Zhu	Low-cost patterned flexible diamond film transfer to copper substrates for direct die attach with enhanced thermal management and stress reduction	Packaging Materials & Processes	ACCEPT
390	Motuan Li, Shunyuan Zha and Yangting Sun	Corrosion Behavior of Cu Pads and Cu/Ti Interfaces in Post-CMP Cleaning for Hybrid Bonding	Quality & Reliability	ACCEPT
391	Yuheng She, Haoran Ma, Meng Sun, Tianhao Guo, Hongyun Wang and Hongwei Liang	Design of high thermal conductivity Titanium-coated diamond/copper composites by the machine learning molecular	AI-Enabled Packaging Technologies	ACCEPT
392	Qicun Lou, Junyu Ye, Jingzhe Liu, Xianlong Wang, Ziyu Liu, Lin Chen, Qingqing Sun and Yabin Sun	Low Temperature In-PI Hybrid Bonding for Temperature-Sensitive 3D Heterogeneous Device Integration	Interconnection Technologies	accept?

393	Bowen Zhang, Jingwen Bai, Yibin Sun and Yunhui Mei	A Low-Parasitic-Inductance Double-Sided Cooling Silicon Carbide Power Module Featuring 3D Mutual Inductance Cancellation	Packaging Design & Modeling	ACCEPT
396	Siyang Li, Fang Yu, Zhenglei Tong and Sen Jiang	Experimental Investigation on the CTE of FR-4 PCBs Under Extreme Temperature Conditions: Role of Copper Volume Fraction and Structural Parameters	Packaging Materials & Processes	ACCEPT
397	Xianlong Wang, Han Jiang, Qicun Lou, Ziyu Liu, Lin Chen, Qingqing Sun and Yabin Sun	Low Temperature C2C Cu/SiO2 Hybrid Bonding with In Passivation Layer	Interconnection Technologies	ACCEPT
398	Sun Yushan, Zhang Ping, Liu Xiaojian, Zhang Ning, Yu Fang and Liu Xiaofan	Study on the Interface Thermal Resistance Characteristics of Three Thermal Pads under Different Pressures	Packaging Materials & Processes	ACCEPT
400	Xiaohui Zhao and Yuxi Jia	Optimization of a Multimodal Deep Learning Model for Warpage Prediction of Fan-Out Wafer-Level Packaging	AI-Enabled Packaging Technologies	ACCEPT
401	Wenqian Li, Donglin Zhang, Sichen Liu, Xiao Ouyang, Wentao Chen, Yuan Zhang, Luke Ma, Shuquan Chen, Xiuchen Zhao,	An atomic scale investigation on twinning structure and surface morphology evolution during deposition growth for silver-based interconnect technology	Interconnection Technologies	ACCEPT
405	Qing Zhou, Daquan Yu and Miao Zhang	Wafer-Level Packaging of a V-Band Air-Filled 3-dB Directional Coupler Using TGV Technologies	Emerging Technologies	ACCEPT
406	Yida Gao, Jiahe Zhang, Guanhua Dun, Ruolong Zhou, Hexuan	A Universal Monolithic Integration Strategy for Perovskite Single Crystals via Ionic-Liquid-Mediated Chemical Welding	Emerging Technologies	ACCEPT
407	Zhanpeng Tian, Jiaqi Song, Yang Fu, Yuan Zhang, Xin Tian, Tao Xu, Luke Ma, Shuquan Chen, Xiuchen Zhao, Gang Zhang and	Development and characterization of ZnO-B2O3-SiO2 glass frit based silver paste for high-performance interconnects compatible to silicon nitride substrates	Interconnection Technologies	ACCEPT
408	Xiaomao Sun, Jian Zhang, Qian Lu, Ming Zhao and You Wang	Research on High-Quality Water-Guided Laser Cutting Process	Advanced Manufacturing	ACCEPT
409	Pengran Yang, Zhaoying Li, Yanqin Jin, Zhongyang Bai and Lianggong Wen	TGV-based calibration standards for D-band terahertz measurements	Advanced Packaging	ACCEPT
410	Liu Chang, Gangli Yang, Danhong Xu, Naiya Yan, Tingting Zhao, Zhiyu Wang and Liyi Li	Impact of Warpage on Misalignment and Voids in 5 μm Pitch D2W Hybrid Bonding	Advanced Packaging	ACCEPT
411	Wei Li, Xiaoyue Ding, Zhaotian Li, Yu Zhang, Chengqiang Cui, Sheng Liu and Zhaofu Zhang	Machine Learning-Assisted Numerical Investigation on Multiphysics Coupling for Copper Electroplating in High Aspect Ratio Through Glass Vias	AI-Enabled Packaging Technologies	ACCEPT

412	Xinyue Zhang, Jianfeng Fan, Zefan Shao and Xiaoliang Zeng	Polymer chain-length distribution engineering for highly flowable and stability gel-type thermal interface materials	Packaging Materials & Processes	ACCEPT
413	He Gao, Huantian Yang, Cong Xi, Yilong Huang, Dongsheng Yang and Kangsen Peng	Research on Solder Joint Reliability of Ceramic Package for SiP Module	Quality & Reliability	ACCEPT
414	Peng Bo and Li Qiaoda	A Modified Darveaux Model for Fatigue Life Prediction of Interconnect Structures in LQFP Devices	Quality & Reliability	ACCEPT
415	Xinpeng Chen, Jinyang Zhao, Yaru Zhang, Lixin Zhan and Baoxia Li	Development of Memory Modules Based on TSV Embedded Reconstitution Technology	Advanced Packaging	ACCEPT
417	Zhenyang Lei, Wei Shen, Huai Zheng, Yu Zheng and Haoyang Zhou	Atomic-Scale Investigation of Interfacial Diffusion and Tensile Creep in Eutectic-Bonded Structures for Optical Module Packaging	Interconnection Technologies	reject?
418	Shikang Liu, Jianfang Zhu, Dongdong Shao, Kunpeng Ding and Tieliang Zhao	Development and Research of Small Packaging and High Heat Dissipation MOS Packaging Structure Based on Embedded	Advanced Packaging	ACCEPT
419	Jiahe Zhang, Yida Gao, Linxuan Li, Yi Zhang, Guanhua Dun, Ruolong Zhou, Hexuan Wang, Zi Wang, Yi Yang, Dan Xie and	Low-Crosstalk Perovskite Thick-Film X-Ray Imaging Detector Array with Row-Column Addressing and CMOS-Compatible Interconnection	Emerging Technologies	ACCEPT
420	Linfeng Chen, Xiaorui Lyu, Jingwen Zang, Shimeng Xu, Xiaochen Xie and Pengrong Lin	Investigation on Void and Extrusion Control of Indium Thermal Interface Materials for Flip-Chip Packaging	Advanced Packaging	ACCEPT
422	Ran Wang, Lianggong Wen, Zhaoying Li, Pengran Yang, Yanqin	Scaling Impact on Transmission Performance of TGV-Based CPW	Advanced Packaging	ACCEPT
424	Ying Tian, Daquan Yu, Shiyuan Wang, Li Yan, Miao Zhang and	Research on Thermal Simulation and Analysis of High-Power Digital SiP Chips	Emerging Technologies	ACCEPT
425	Shi Chen, Xiangyang Shi, Yaning Lin, Yuanpeng Li, Lipeng Zheng and Rong Zeng	Low-Temperature Fabrication of (001)-Oriented Large-Grain Cu for Preferential Orientation Control of Interfacial Cu_6Sn_5 in Micro-Interconnections	Packaging Materials & Processes	ACCEPT
427	Gangli Yang, Liu Chang, Yanan Li, Yi Wang, Tingting Zhao, Naiya Yan and Liyi Li	Enabling 5 μm Pitch D2W Hybrid Bonding: From CMP to Bonding	Interconnection Technologies	ACCEPT
428	Aleksandra Sienkiewicz, Abhinay Nallam, Leon Miller, Aline Jarofski, Robert Miller, Eva Kaiser and Vemal Manikam	High-Performance Novel PE340 Ag Sinter Paste for Die Attach with Excellent Workability and Outstanding Wet-Pad Edge	Interconnection Technologies	accept?

430	Hongbin Shi, Shuangqin Xie and Jinming Fu	Achieving Low-Cost Wafer level Packages Using Solder Balls with High Temperature Cycling Reliability	Quality & Reliability	ACCEPT
431	Qiang Ma, Weidong Chen and Yue Dong	The analysis of the weld microstructure and the optimization of seam welding parameters based on NiP-Ni heterogeneous coating by resistance fusion welding	Packaging Materials & Processes	ACCEPT
432	Sijie Yang, Yufeng Li, Hanbing Liu, Zhonghua Yang, Qingji Zhao, Yu Sun, Wenbo Luo and Wangli Zhang	Optoelectronic Co-Design and Packaging-Dependent Signal Integrity Analysis of Micro-LED Arrays for Low-Power Interconnects	Optoelectronics and New Display	ACCEPT
433	Gaochen Yang, Xing Hu, Chenlong Ma, Wenhao Shi, Langlang Xu, Xinyu Huang, Shengjie Lv, Mingjun Sun, Zili Li, Lei	Coupled Effects of Annealing Temperature and CMP Dishing on Cu-Cu Hybrid Bonding Interface Quality in 3D Heterogeneous	Interconnection Technologies	ACCEPT
434	Fanbo Meng, Jushang Guo, Zhongda Gao and Jianan Dang	Unveiling the Coupled Effects of Wafer Gap and Striking Force on Bonding-induced Lithography Overlay	Packaging Design & Modeling	ACCEPT
435	Wangyong Chen, Yaojie Mo, Weizhi Li and Linlin Cai	Physics-Informed POD-Guided Deep Learning Framework for Sparse Thermal Field Reconstruction	AI-Enabled Packaging Technologies	ACCEPT
436	Liao Wenyuan, Huang Zibin, Huang Qinwen, Lu Guoguang, Lai	Degradation behavior and non-destructive failure analysis of GaN-based blue laser diodes	Quality & Reliability	ACCEPT
437	Cheng Peng, Yihao Meng, Wenxuan Ma, Yetong Zhang, Siwei	In-situ XPS Analysis of Hydroxyl Group Generation in Plasma Activation Technology	Advanced Packaging	ACCEPT
438	Kaihua Xie, Jingtao He, Qiang Huang, Fengqing Lu, Mingkang Zhang and Yifu Liang	A composite spiral pillar structure fabricated by laser powder bed fusion for enhancing boiling heat transfer performance	Emerging Technologies	ACCEPT
439	Liu Xiaofan, Zhang Ping, Zhang Ning, Liu Xiaojian, Yu Fang, Zhang Yuqing and Sun Yushan	Research on PCB Thermal Simulation Model Optimization Based	Quality & Reliability	ACCEPT
443	Miaosen Yang, Xinrui Li, Yue Kang and Jicun Lu	Study on Laser Marking Process and Reliability for Power Modules	Quality & Reliability	ACCEPT
444	Letong Zhang, Huashi Yang and Yanpeng Gong	Analysis of Crack Evolution in Through Glass Via (TGV) Structure Using TPF-CZM Model	Packaging Design & Modeling	ACCEPT
445	Yu Zhao and Yong Xiao	Rapid brazing of graphene film using an ultrasonic-resistance energy field	Interconnection Technologies	reject?
446	Wenlong Shao, Lin-Jie Liu and Zhen-Tao Yang	Design of a Ka-Band BGA Package Based on High Temperature	RF Electronic Packaging	ACCEPT

448	Liang Mingxi, Yang Jiming, Lv Weishan, Liu Jiaxin, Peng Yang and Xu Chunlin	Fabrication of electroplated Sn-Cu foam for transient-liquid-phase bonding	Interconnection Technologies	accept?
450	Yihao Meng, Haibo Yang, Fei Ding, Yu Zhang, Yudong Yang, Qiushi Kang, Yang Liu, Renxi Jin, Liqaing Cao and Qidong Wang	NaOH-Based Wet Chemical Activation for SiCN Dielectric Bonding	Interconnection Technologies	ACCEPT
451	Xiaolian Liu, Xiaoliang Ji and Yishu Wang	Tuning Twin Formation in β-Sn: Effects of Indium and Cooling Rate in SAC305+xIn Interconnects	Emerging Technologies	ACCEPT
452	Guoliang Liu, Guoliang Li, Xuewei Zhao and Guangbao Shan	Intelligent Multi-Physics Collaborative Design and Layout Optimization for Irradiated Inertial Microsystems Based on Cascade Surrogate Models	AI-Enabled Packaging Technologies	ACCEPT
454	Cong Jiang, Baoyuan Wang and Hao Wang	High-Performance Solar-Blind Photodetector Based on Mg-N: β-Ga2O3/GaN Heterojunction	Optoelectronics and New Display	ACCEPT
456	Hongqin Wang, Yan Ren and Shengze Zhou	Experimental Study on Thermal Fatigue Reliability of PBGA Solder Joints under Router Depaneling Stress	Quality & Reliability	ACCEPT
457	Bo Ching Wong, Ying Xin, H.P. Tang, Ka Hei Lam, Yandy Ma, Anthony Mannion, Robert Voyle and M.W. Fu	Deposit Ti6Al4V on Glass Substrates by Cold Spraying at Near-straight Angles	Packaging Materials & Processes	ACCEPT
458	Liantao Liu and Qian Jiang	Influence of Substrate Modeling Strategies on Package Warpage Prediction	Packaging Design & Modeling	ACCEPT
460	Penghui Pan, Haijuan Li, Lixin Zhan, Xuan Zhang, Zhipeng Mei and Genwang Wang	Research on Non-destructive Fault Diagnosis of TSV 3D Stacked Packaging	Quality & Reliability	ACCEPT
462	Lei Yang and Yexiong Huang	Optimization and Reliability Investigation of Nano-Copper Sintering Technology for SiC MOSFET Devices	Packaging Materials & Processes	ACCEPT
464	Zhongda Gao, Jushang Guo and Fanbo Meng	Impact of Crystallographic Orientation on High-Order Lithography Overlay in Direct Wafer to Wafer Bonding	Packaging Design & Modeling	ACCEPT
465	Yunhao Zhang, Shenghao Jin, Boxiang Wang, Kaihuan Zhang, Peikun Liao and Wenqing Yan	Three-Dimensional Crosslinked PEG-Based Composite Phase Change Material for Enhanced Thermal Management in	Emerging Technologies	ACCEPT
466	Hengtong Guo, Pengrong Lin, Hexiong Qi and Wei Zhou	Constitutive Behavior of Sn-37Pb under Thermo-Mechanical Coupling Conditions	Quality & Reliability	ACCEPT
467	Jian-Yun Qin, Min-Bo Zhou, Hao-Ze Zong, Bin Hou and Xin-Ping Zhang	One-Pot Aqueous-Synthesized Sub-Micron Cu Particles Enabling Air-Sinterable Paste for Wide-Bandgap Die Attachment	Packaging Materials & Processes	ACCEPT

468	Yang Cheng, Binbin Qi, Xuehao Zhou, Tianze Li, Long Teng, Tian Lin, Zhengxun Hu and Rong Sun	Mechanism of Adhesive Residue Formation in Laser Debonding and Development of a Plasma-Assisted Cleaning Process for	Packaging Materials & Processes	ACCEPT
469	Haijie Chen, Jincheng Zhang, Yuanyuan Yang, Yusheng Zhao,	Study on XDFOI-O Package with Fine Pitch RDLs and Cost Down	Advanced Packaging	ACCEPT
470	Jinxin Huang, Xiaomeng Huang, Xiangxi Mao and Chen Ji	Research on warpage characteristics of ultra-large multi-chip FCBGA package	Packaging Design & Modeling	ACCEPT
471	Jingxue Feng, Hongbin Shi and Jinming Fu	Reliability-Oriented Design Optimization for Low Cost Panel-Level Packages (PLP)	Packaging Design & Modeling	ACCEPT
472	Siqi Chen, Yaohua Xu, Yi Wang and Han Jiang	Characterization of Solder Interconnections Formed by Cu–Sn	Advanced Manufacturing	ACCEPT
473	Gong He, Wang Zhichao, Cao Meng, Lin Ye, Liu Binquan and Yao Yao	Large-Area Bare Copper-Sintered Nano-Silver Direct Bonding Technology and Its Reliability	Quality & Reliability	ACCEPT
474	Jian Cheng	Experimental and numerical analysis of a fan-out BGA Chip on PCB reliabilities under board level drop test loads	Packaging Design & Modeling	ACCEPT
475	Yuqi Jiang, Hongbin Shi and Jinming Fu	Comprehensive analysis of PI Crack for a FOECP Package under Board Level Temperature Cycling Test	Packaging Design & Modeling	ACCEPT
477	Rui Ma, Jingyi Zhao, Meiying Su, Yang Yang, Jun Li, Qidong Wang and Liqiang Cao	Interface Bonding Reliability Characterization of Heterogeneous Interfaces in PSiP Embedded Component Packaging	Quality & Reliability	ACCEPT
478	Xingzhe Wang, Fangcheng Cao, Xingyan Zhao, Yang Qiu, Shaonan Zheng, Yuan Dong, Qize Zhong and Ting Hu	Self-alignment of Silicon Bridge based on Photoresist Reflow	Emerging Technologies	ACCEPT
479	Guanghao Wang, Susu Li, Yaohua Xu, Yi Wang and Han Jiang	Enhanced Low-Temperature Cu–Cu Bonding with Mixed-Size Cu	Advanced Manufacturing	ACCEPT
480	Chaoran Yang, Leo Huang, David Ren, Eric Cao and Fubin Song	Thermo-mechanical Assessment of Epoxy-filled Vias in High-Density Interconnected PCBs for Advanced Telecommunication Application	Quality & Reliability	ACCEPT
481	Xinyu Zhang	Challenges during the development of High CTI Epoxy Mold Compounds (EMC) in high voltage devices for automotive applications	Packaging Materials & Processes	ACCEPT
482	Jiabin Liu and Jian Cheng	Thermal Warpage Simulation of BGA Chip Considering Full Packaging Process and Underfill Property Test	Packaging Materials & Processes	ACCEPT

483	Peng Li, Xiaozhen Sun, Wenjie Ding, Kunhong Chen and Shuyang Yuan	Photonic-Electronic Hybrid Architectures for Cryogenic Systems: From Quantum Information Processing to Space Exploration	Optoelectronics and New Display	ACCEPT
484	Zongshuai Li, Yaohua Xu, Yi Wang, Shuibao Liang and Han Jiang	Interfacial Engineering for Enhanced EGaIn-Based Bonding: Role of Fluxes and Surface Topography on Wetting, Spreading, and Adhesion Strength	Advanced Manufacturing	ACCEPT
486	Bo Peng, Qian Lou, Huanjun Zheng, Yifan Yu and Yang Wang	Root Cause Analysis of Non-EOS Induced Massive Burn-out Failure of LED Light Bars	Quality & Reliability	ACCEPT
487	Ruoda Wang, Jinglin Shi, Zhiwei Fu and Qiang Hu	Interface Evolution and Mechanical Properties of Fe and B Containing Lead-free Solder Alloys	Packaging Materials & Processes	ACCEPT
488	Yuanjie Cheng, Xing Qiu, Qianwen Xu, Mian Tao and S. W. Ricky Lee	Fabrication of a Quantum Dot Color Conversion Layer by Laser Patterning for Full-color Micro-LED Displays	Optoelectronics and New Display	ACCEPT
489	Haohan Tan, Dequan Jiang, Zhen Chen and Shujuan Liu	Research on Local Geometric Optimization of Top Microchannel Cold Plates for 2.5D GPU Systems	Advanced Packaging	ACCEPT
490	Yiwei Dong, Yan Zhong and Yunwen Wu	Fabrication of a Multifunctional Adhesion Layer for Glass Substrate Electroplating	Interconnection Technologies	reject?
491	Xin Tang, Ran Lu, Lin Cui, Xianxing Ju, Jiaqi Ni and Mingxiang Chen	Quasi-Hermetic Sealing Technology for Three-Dimensional Ceramic Substrates Using Adhesive Bonding	Packaging Materials & Processes	ACCEPT
492	Honghui Li, Yu Ren, Shiqi Jia, Ruiwen Liu, Binbin Jiao, Yanmei Kong and Yuxin Ye	The Study of Thermal and Stress Field Inversion Techniques Based on Sparse Test Data	Packaging Design & Modeling	ACCEPT
493	Qi An, Mingming Ji and Xinyan Lu	Research on Vertical Interconnection Technology and Reliability Based on High-Coplanarity Micro-Copper Pillars	Interconnection Technologies	ACCEPT
494	Weiqiang Li, Wenzhe Wang, Dongchang Ma, Changlong Ye, Huitao Liu, Guannan Yang, Chengqiang Cui, Yu Zhang and Guanghan Huang	A Copper Foil-Based Imprinting Method for Fabricating Embedded Lines with Enhanced Reliability	Advanced Manufacturing	ACCEPT
495	Zhipeng Niu, Ke Yu, Sheng Liu, Dahai Lu, Xianli Xie, Jiajun Zhou and Penghui Guan	Reliability Simulation of Glass Substrate Modules under Mechanical Shock Loading and Optimization Design of Encapsulation Structures	Packaging Design & Modeling	ACCEPT
496	Zhenzhong Yang and Xiangyu Sun	Design of Magnetic Sensors and In-situ Current Sensing Techniques for Heterogeneous Integration Microsystems	Packaging Design & Modeling	ACCEPT

497	Yaxian Huang, Qimeng Sun, Zhiqiang Tian, Yang Xi, Yuhua Huang and Shizhao Wang	Thermal Cycling Fatigue Life Prediction of Advanced Packaging Solder Joints Based on Finite Element–Physics-Informed Neural Network Coupling	AI-Enabled Packaging Technologies	ACCEPT
498	Qianying Guo, Haoliang Zhang, Qiang Xiao, Guiqin Chang and	Analysis of Thermal-caused Delamination in Transfer Molded Power Module	Power Electronics & Energy Electronics	ACCEPT
500	Jinshun Huang, Qiuyan Huang, Wei Cen, Yaohua Xu, Han Jiang	Pressureless Sintering of Ag Paste on Cu Interface in N2 Atmosphere Assisted by Silver Acetate	Interconnection Technologies	accept?
502	Wenkai Wang, Xiaoting Lin, Wei Cen, Yaohua Xu, Han Jiang and Junjie Li	Sintered Copper Films for Interconnection Packaging in PCB-Embedded Power Module	Interconnection Technologies	accept?
504	Wang Jiang, Mifeng Liu and Xinyu Li	Finite Element Simulation-Based Process Reliability Analysis of Thermosonic Flip-Chip Bonding for Gold Bumps	Quality & Reliability	ACCEPT
505	Wenzhe Xu, Yuxin Ye, Yanmei Kong, Ruiwen Liu, Shiqi Jia, Zhiguo Qu and Binbin Jiao	Zoned Valve-Regulated Thermal Management Technology for High-Power Multi-Chip Arrays	Emerging Technologies	ACCEPT
506	Qi Qiao, Jing Chen, Yan Luo, Bin Sun and Kai Chen	Impact Evaluation of Component Floorplan and Placement on the Channel Consistency of Mixed-Signal System-in-Package via Simulation	Quality & Reliability	ACCEPT
507	Peng Wu, Ruyu Tian, Yangguang Shan, Shuhan Dong, Tao Deng,	High-Throughput Thermodynamic Screening of Multicomponent	Packaging Materials & Processes	ACCEPT
509	Ziyan Guan, Mingtai Li, Yu Wang, Fanqiang Zeng, Menglin Yao	A novel modeling method for modified region in stealth dicing and its application in optimizing process parameter	Packaging Design & Modeling	ACCEPT
510	Yajun Zhang, Jianguo Zhang, Qiang Chen, Junyuan Luo and Guangyao Li	A Methodology of Optimizing Power Noise Coupling on Die-Package-PCB for High-Speed Digital-Analog ICs	Packaging Design & Modeling	ACCEPT
511	Xuelang Gao, Jia Xiong, Xiaoxin Li and Hang Zhou	Impact of Solder Mask Process Parameters on Cure Gradient and Substrate B-HAST Reliability	Quality & Reliability	ACCEPT
514	Byeongchan Kim, Junha Baik, Ha-Young Yu, Xuyang Yan and Dongjin Kim	Bonding reliability and process optimization for direct-cooling power module implementation depending on large-area heat sink structure	Packaging Design & Modeling	ACCEPT
515	Yimo Wang, Jiefei Gu, Ke Li, Lei Su and Xuefei Ming	Efficient Thermal-Aware Chiplet Placement of 2.5D Heterogeneous Systems Using an Improved Multi-Fidelity Bayesian Optimization Framework	AI-Enabled Packaging Technologies	ACCEPT
517	Jinmei Zhu, Augusto-Daniel Rodrigues, Muhammad-Hassan Malik, Shyamal Roy, Roman Geier and Ali Roshanghias	Through-silicon via (TSV) filling with polymeric materials; a comparison study	Packaging Materials & Processes	ACCEPT

518	Gaowei Xu, Tao Fan, Kelaiti Xiao and Dalong Chen	Fabrication of Superconducting Through-silicon-vias by Using Dry Etching Method for Three-dimensional Multi-chip Module of Single-flux-quantum Circuits	Emerging Technologies	ACCEPT
519	崔 霖, Tang Xin and Ni Jiaqi	Enhancement of Metallization Bonding Strength in DPC Silicon Nitride Substrates via TiO_2 Interlayer	Packaging Materials & Processes	ACCEPT
520	Lu Li, Yuting Zhang, Xingkang Yang, Xujing Nan, Penghui Pan, Baoxia Li and Daowei Wu	Numerical Investigation on Thermal Fatigue Reliability of CCGA Devices under Temperature Cycling Conditions	Packaging Design & Modeling	ACCEPT
521	Ruize Zhang and Jian Cheng	Transient thermal–mechanical coupling simulation of IC product resistance welding process and its influence on the fatigue life of the wire bond solder joint during temperature cycling test	Packaging Design & Modeling	ACCEPT
522	Weibin Wang, Fan Zhang, Xiaofei Zhang, Xiaowei Liu, Zhe Li and Rong Sun	Hybrid Microstructured and Thermally Stable Cu Electroplating via N-NDR Polymer-Additives for Cu-Cu Direct Bonding	Packaging Materials & Processes	ACCEPT
523	Junha Baik, Byeongchan Kim, Ha-Young Yu and Dongjin Kim	Power electronics chip rework without thermal and mechanical process	Power Electronics & Energy Electronics	ACCEPT
524	Xuanyu Ding, Yudong Yang, Chi Zhang, Hongchao Zhang, Fei Ding, Yu Zhang, Renxi Jin, Haibo Yang, Qiushi Kang,	A Multiscale Simulation Study on Interfacial Crack of Dielectric in Hybrid Bonding Structure	Advanced Packaging	ACCEPT
525	Yuqing Lu, Lian Chen, Huiyuan Liu and Jun Wang	Layout Optimization of Solder Ball Array for Fatigue Life Enhancement in Board-Level Radar Packages by FEA	Packaging Design & Modeling	ACCEPT
526	Chunhua Zhang, Canyu Liu and Changqing Liu	Reliability evaluation of Ag@diamond composite sintering paste for Power Devices	Packaging Materials & Processes	ACCEPT
527	Yulin Hu, Houzhao Wan, Zhengyang Li, Junwei Zhang and Daohong Yang	Graphene electro-absorption modulator based on slow-light effect	Optoelectronics and New Display	ACCEPT
528	Junwei Zhang, Houzhao Wan, Yulin Hu, Zhengyang Li and Daohong Yang	Design of Electro-optic Modulator with Slit Silicon-Lithium Niobate Waveguide Based on Electrode Structure	Optoelectronics and New Display	ACCEPT
529	Yansong Li, Shurong Cao and Sunan Ding	Thermal Stress and Parameter Sensitivity Analysis of nTSVs in BSPDN via Sub-modeling Technique	Advanced Packaging	ACCEPT
530	Peiyang Li, Ruyi Li, Guanmei Liu, Shiqi Liu, Pai Peng, Bo Yi and Wenbo Luo	Design of a V-Band AiP Electric Dipole Antenna and Array on Glass Substrate	RF Electronic Packaging	ACCEPT

532	Tian-Yu Bao, Rong An, Chang-Ming Cao, Zi-Yao Yuan, Zhang-Hong Wang, Hui Zhang and Cong Liu	A Physics-Guided Gradient Boosting Approach for Few-Shot Prediction of Strain Energy in BGA Solder Joints	Quality & Reliability	ACCEPT
533	Feng Qin, Xinzhu Yan and Zhicheng Lei	Low-Stress Structure Optimization of Double-Sided Sintering for Power Modules by Taguchi-Grey method	Packaging Design & Modeling	ACCEPT
534	Yinghao Meng, Lei Gao, Xinzhu Yan, Feng Qin and Juntao Li	Design and Realization of 7kV Pulse Power Module based on 3-D Stacked Package	Packaging Design & Modeling	ACCEPT
535	Haoyuan He, Yongli Shen, Yong Wang, Yadong Xu, Xi Lu, Yougen Hu and Rong Sun	Microencapsulated Aromatic Amine-Based Latent Anisotropic Conductive Adhesives for High-Reliability UHF RFID Tag Packaging	Packaging Materials & Processes	ACCEPT
536	Jianchao Liang, Ruyu Tian, Jiaming Liu, Yiping Wang, Chuanfang Zi and Yanhong Tian	Improvement in drop reliability of SnAgCu-based solder joint induced by enhanced solder ductility and inhibited interfacial IMC growth	Quality & Reliability	ACCEPT
537	Xiaodan Chen and Yan Xue	A Thermal Test Vehicle for Integrated Evaluation of Thermal, Material, and Process Reliability in Advanced 3D Packaging	Quality & Reliability	ACCEPT
538	Feng Yiming and Peng Bo	A Dual-Parameter Peeling Model Tailored for Adhesive Interfaces Between Elastic Film and Rigid Substrate in Redistribution Layer	Interconnection Technologies	ACCEPT
539	Cong Liu, Jinling Huang, Yaya Liang and Pingan Du	A homogenized Equivalence Modeling method for Multi-Physics	Quality & Reliability	ACCEPT
540	Zhaochang Peng, Sheng Liu, Dahai Lu, Yu Chen, Qu Zeng and Bo Zhao	High-Fidelity Fluid-Structure Interaction Analysis for Fragmentation Risk Assessment and Process Optimization of Ultra-Thin Wafers During Fluid Entry	Packaging Design & Modeling	ACCEPT
542	Sichen Liang, Zhiheng Huang, Hui Yan and Yang Liu	Dominant Multiphysics Effects Governing In-Plane Distortion in Direct Wafer Bonding	Packaging Design & Modeling	ACCEPT
543	Junhao Yang, Yun Teng, Yunyun Sun and Sheng Liu	Study on the Evolution Mechanism of Micro-Bump Contact Resistance in Chiplet Packaging Considering Electro-Thermo-Mechanical Coupling	Packaging Design & Modeling	ACCEPT
544	Liang Zhang, Zhensong Li, Cunlong Li and Weixin Li	A Residual-Based Wide-Scale Equivalent Modeling Method for	Advanced Packaging	ACCEPT
545	Wei Cheng, Qing Wang, Tao Lu and Yang Peng	High-Rate and Uniform Copper Jet Electrodeposition Through Nozzle Geometry Optimization	Packaging Materials & Processes	ACCEPT

547	Yuchen Wei, Susu Li, Leyin Zhang, Han Jiang, Zhihong Zhong,	Influence of Interfacial Energetics on Void Morphology and Closure in Cu-Cu Bonding	Interconnection Technologies	ACCEPT
551	Zicheng Huang, Zhiheng Huang, Hui Yan and Yang Liu	Beyond the Black Box: Physics-Aware Failure Analysis of Microelectronic Devices via Microstructural Hierarchy Descriptor	AI-Enabled Packaging Technologies	ACCEPT
552	Changhao Chen, Songzhao Gu, Xiaorui Lv, Xiaochen Xie, Pengrong Lin and Shimeng Xu	Hemiwicking Induced Sidewall Intermetallic Compounds (IMC)	Interconnection Technologies	ACCEPT
553	Zhu Zeli, Huo Jiaren, Zhang Chao and Zhang Li	Impact of Material Properties and Surface Roughness on Signal Integrity in Glass Substrates: An Impedance and S-Parameter Analysis	Packaging Design & Modeling	ACCEPT
554	Xinyue Shen, Xuefeng Wu, Chenyi Dai, Jinyue Li, Zhiyi Song, Chaoyang Wang, Liyang Zhao and Guizheng Hao	Microstructural Evolution of Electroplated Silver-Based Alloy Interconnects for Multilayer Stacked Packaging	Interconnection Technologies	ACCEPT
555	Guoli Zhang, Yafei Wang, Hong Li and Shengnan Li	Research on Reliability and Thermal Characteristics of High Thermal Conductivity Molding Compound for High-Density Packaging	Packaging Materials & Processes	ACCEPT
556	Xuefeng Wu, Chenyi Dai, Jinyue Li, Zhiyi Song, Chaoyang Wang, Liyang Zhao, Guizheng Hao and Xinyue Shen	Electrochemical Migration Reliability of Electrodeposited Ag-Based Alloy Thin Films in Hermetic 3D Stacked Packaging for Aerospace Applications	Quality & Reliability	ACCEPT
557	Tao Lu, Han Chen, Qing Wang, Jiuzhou Zhao, Wei Cheng and Yang Peng	Interfacial Enhancement Mechanisms in Electroless Copper Plating on Cyanate Ester Resin: Role of Stepwise Oxidation and Catalytic Activation	Quality & Reliability	ACCEPT
558	Minsu Kim, Junha Baik, Xuyang Yan and Dongjin Kim	Scale dependent hillock generation of silver-plated surfaces with barrier layers	Power Electronics & Energy Electronics	ACCEPT
559	Yang Li, Changsi Wang, Le Dong, Yanming Zhang, Jiacheng Gao and Yangyang Li	An Advanced ANN-based Modeling Method with Reflection-Coefficient-Weighted Loss for Broadband RF Interconnects in 3D Packages	Packaging Design & Modeling	ACCEPT
560	Xiaoran Cheng, Zhaoxi Wu, Jun Guo, Xinran Lv and Qifei Yuan	Analysis of Packaging Failure Mechanism and Research on Reliability Improvement Strategies in BGA Flip-chip Devices	Packaging Materials & Processes	ACCEPT
561	Bin Hou, Jian-Yun Qin, Hao-Ze Zong, Min-Bo Zhou and Xin-Ping Zhang	Superb sinterability of the Cu paste consisting of Cu micro-nano particles synthesized by a mild one-pot aqueous method for low-temperature in-air die attachmen	Packaging Materials & Processes	ACCEPT

562	Xiaoran Cheng, Zhaoxi Wu, Jun Guo, Qifei Yuan and Xinran Lv	Study on the Long-term Reliability of Au-Al Heterogeneous Bonding under High Temperature Stress	Packaging Materials & Processes	ACCEPT
563	Zhenyu Lei, Canyu Liu, Mingxiang Chen and Changqing Liu	Fabrication of Multilayer Circuit on DPC Ceramic Substrate with Polyimide	Packaging Materials & Processes	ACCEPT
564	Songtang Li, Wanli Li, Weiwei Zeng and Junfeng Sun	Semi-Sintered Copper Pastes with High Conductivity and Strong Adhesion for Printed Electronics	Emerging Technologies	ACCEPT
565	Xiangcheng Wang, Haoran Ma and Tianhao Guo	Electroplating process control and reliability of nanotwinned-copper RDLs for 2.5D/3D Packaging	Packaging Materials & Processes	ACCEPT
566	Ha-Young Yu, Junha Baik, Byeongchan Kim, Xuyang Yan and	Reliability degradation of solder joints depending on IMC fraction in ultra-fine-pitch interconnections	Interconnection Technologies	accept?
567	Kangsen Peng, Cong Xi, Yilong Huang, Yuan Huang, Jianxing Shi, Dongsheng Yang and He Gao	Investigation of the failure mechanism for delamination in conductive adhesive induced by protective adhesive layer based on simulation and verification	Quality & Reliability	ACCEPT
568	Zhang Yanming, Yang Li, Le Dong, Changsi Wang, Jiacheng Gao, Dongyang Lei and Yangyang Li	Statistical Modeling and Application Method of RF Passive Transmission Based on Process Feature Embedding	Packaging Design & Modeling	ACCEPT
569	Junxiong Lu, Zenghang Yan, Xiaojun Xie, Zhendong Xue, Jianan Dang, Jushang Guo and Fanbo Meng	Topography-Based Wafer Distortion Characterization for Advanced Hybrid Bonding: A Low-Cost, IR-Constraint-Free Measurement Solution	Advanced Packaging	ACCEPT
570	Zhubin Hua, Hongbin Shi and Jinming Fu	A Novel Thermal Via Array Design for Enhancing Heat Dissipation in High-Power Wafer-Level Packages	Packaging Design & Modeling	ACCEPT
571	Yong Zhang, Yifei Duan, Xiaohui Guo, Zhexin Feng, Bin Li and Yan Zhang	Improving Thermal Properties of PDMS by Adding Vertically Aligned Graphene	Packaging Materials & Processes	ACCEPT
572	Kaiwen Luo, Han Jiang, Lin Chen, Qingqing Sun, Yabin Sun and Ziyu Liu	A Novel Polishing Slurry for CMP Process of Cu/SiO_2 Hybrid Interface	Interconnection Technologies	accept?
573	Lin Zhang, Hongbin Shi and Fei Liu	Mitigation of Sidewall Cracking in eSiFO Packages via Advanced DBG (Dicing Before Grinding) Process	Packaging Materials & Processes	ACCEPT
574	Martin Letz, Guangjun Zhang, Fabian Wagner, Vanessa Gläßer, Inge Burger, Volker Seibert and Timo Luchs	Glass substrates enable advanced semiconductor packaging: Design rules for via-via distances based on mechanic reliability.	Advanced Packaging	ACCEPT
575	Jian Wang, Zhiguo Liu, Dayong Zheng, Kun Jiang and Chuanjin	Effects of Different Underfill Methods on the Reliability of CBGA Packages	Packaging Design & Modeling	ACCEPT

577	Jiaqi Ni, Ke Yang, Lin Cui, Xin Tang, Yang Peng and Mingxiang Chen	Thermal–Mechanical Coupling Analysis and Optimization of CVD Diamond Heat Sink in High-Power Semiconductor Laser COS	Packaging Design & Modeling	ACCEPT
578	Bo Peng, Huanjun Zheng, Yang Wang, Qian Lou and Yifan Yu	Analysis and Mechanism Investigation on Delamination Between Acrylic Resin Encapsulant and Bracket in LEDs	Quality & Reliability	ACCEPT
579	Kai He, Yi Tao Li, Xiao Ma and Xin Ping Zhang	Interfacial Delamination and Thermo-mechanical Reliability Analysis of Embedded Pt-RTD Structures for Accurate Wafer-Level Temperature Monitoring	Emerging Technologies	ACCEPT
580	Miao Wang, Jihua Zhang, Libin Gao, Hongwei Chen, Xingzhou Cai, Yong Li, Dongbin Wang, Shuang Li, Ting Liu, Bin Peng	Influence of centerline segregation porosity on electromigration failure in copper pillars of Through-Glass Via (TGV) interconnects	Quality & Reliability	ACCEPT
581	Yu Cai, Zhiming Chen, Ziyue Zhang, Yuwen Su, Han Wang and	Modeling and Optimization of TSV Cu Electroplating Process for Void-Free Filling	Packaging Design & Modeling	ACCEPT
582	Hongbin Shi, Yanning Dang and Zhubin Hua	Synergistic Design-Process Optimization for Suppressing Solder Ball Voids in Wafer-Level Packaging (WLP) Ball Attach Processes	Packaging Materials & Processes	ACCEPT
583	Quanlu Zhao, Jingyi Zhao, Chuan Chen, Jun Li, Xinyu Zhang, Zhongyao Yu, Shanjun Ding, Xiaomeng Wu and Qidong Wang	Crack Propagation Risk Assessment in High Aspect Ratio TGVs in Glass Substrates during Annealing and Lamination	Quality & Reliability	ACCEPT
584	Huang Z, He D.J, Ren J, Huang F.F and Huang M.L	Indium and Bismuth Co-Additions: A Synergistic Approach to Improving Shear Performance of SACQ Solder	Advanced Packaging	ACCEPT
585	Junkai Wang, Shenghao Jin and Boxiang Wang	Dynamic thermal radiative management based on reversible metal electrodeposition and dielectric-absorber-dielectric structures	Emerging Technologies	ACCEPT
586	Ziyang Ou and Xiaohong Wang	Broadband Electrical Analysis of Hybrid Bonding Interface Non-Idealities in 3D RDL-TSV Interconnects	Quality & Reliability	ACCEPT
588	Shaowei Liu, Ziyang Ding and Liyi Li	Investigation of Crack Formation Mechanism in PECVD Silicon	Advanced Packaging	ACCEPT
589	Naiya Yan, Jiarui Li, Liu Chang, Gangli Yang, Shaowei Liu and Liyi Li	A non-destructive metrology solution for prediction of bonding void and reliability in fusion and hybrid bonding	Advanced Packaging	ACCEPT
590	Ziqiang Xu, Heran Zhao, Jianqiao Liu, Shizhao Wang, Hongjun	A Visual Perception Flapping-Wing Micro Air Vehicle Integrating AI Physical Models	AI-Enabled Packaging Technologies	ACCEPT

591	Shaoyi Liu, Lu Hao, Shuai Li, Donghua Xu, Lirong Yuan, Congsi Wang and Kui Li	Research on the Effect of Crack Defects on Transmission Performance of BGA Interconnection and Its Compensation Methods	Quality & Reliability	ACCEPT
592	Jing'Long Zheng, Bingchen Li, Weicheng Wu, Yuhua Huang and Chengxin Wang	A Physics-Informed Conditional Diffusion Model for Prediction of Abrasive Particle Trajectories and Distribution in CMP Process	AI-Enabled Packaging Technologies	ACCEPT
593	Lu Hao, Shaoyi Liu, Kui Li, Zhihong Liu and Kangrong Li	Research on Heat Dissipation Enhancement Technologies for GaN-on-Si RF Transistors	Quality & Reliability	ACCEPT
594	Le Dong, Qian Lu, Jian Zhang, Changsi Wang, Yang Li and Ming Zhao	A CO-Type Quasi-Coaxial Shielded TCV Structure for High-Density 3D Packaging	Packaging Design & Modeling	ACCEPT
595	Lihui Xv, Chuhan Xie, Jinlong Peng, Yve Xiao and Liyi Li	Enabling Continuous Seed Layers in High Aspect Ratio TSVs via Hybrid and Electroless Deposition Strategies	Interconnection Technologies	accept?
598	业惠 蒙, 海东 闫 and 财富 李	Optimization of Low Inductance and High Current Sharing for SiC Multi-Chip Power Modules Based on 3D Topological Interconnection of Cu-Clip	Interconnection Technologies	reject?
599	Jiuzhou Zhao, Meiqi Ye, Hongjin Zhang and Yang Peng	Advanced Cold-Sintered Phosphor Ceramics@Cu Converters	Optoelectronics and New Display	ACCEPT
600	Chenglin Yang, Wenwen Zhang, Jun Li, Yunyan Zhou, Meiying Su, Gang Song and Qidong Wang	Packaging and Performance Testing of ADC in SiP with Integrated "Collection-Storage-Computation-Communication" Functions	Advanced Packaging	ACCEPT
601	Che Song, Na Yan, Ruibo Cao, Yiying Bao, Jian Song, Xiangan	Design of High Energy UI-Core Inductor for Four-Switch Buck-Boost Converters	Power Electronics & Energy Electronics	ACCEPT
603	Cheong Ha Jung and Gu-Sung Kim	Statistical Analysis of TCV Structural Effects on High-Frequency Electrical Characteristics of Fine-Pitch Ceramic Substrates at 5 GHz	Advanced Packaging	ACCEPT
604	Fupeng Huo, Chuantong Chen, Pan Liu, Peng Zhang, Dongjin	Enhanced thermal shock reliability of sintered AgAl composite paste applied in power device packaging	Power Electronics & Energy Electronics	ACCEPT
606	Qihang Yu, Jiawei Deng, Siyuan Wang, Zhi Ren, Pu Xu and Xinping Zhang	Design of a High-performance Fluxless Solder Paste Used for Formic Acid Vacuum Reflow Process in Power Device	Packaging Materials & Processes	ACCEPT
607	Bo Sun, Yue Sun, Jianwen Sun and Huaiyu Ye	Thermal Co-Design and Advanced Cooling Strategies for Next-Generation RF and Heterogeneous Integration	RF Electronic Packaging	ACCEPT

608	Hui Xiao, Jie Luo, Jiahao Liu, Fangzhou Chen and Xiaodong Chen	Damage Behaviour and Reliability Evaluation of Vertical Interconnection Solder Joints in RF SiP Modules	Quality & Reliability	ACCEPT
609	Weijie Cheng, Jian Zhang, Ming Zhao, You Wang and Qian Lu	Research on High-Precision AuSn Eutectic Sealing Process for 3D SiP	Packaging Materials & Processes	ACCEPT
611	Xuan Dai, Fang Li and 啸风 陈	Comparative Study on Thermal Performance of Silicon Nitride-Based Micro-channel Cooling Structures for High-Power IGBTs	Packaging Materials & Processes	ACCEPT
613	Yule Liu, Sichen Liu, Luke Ma, Zhongshuo Yang, Yuan Zhang,	Atomistic Mechanism of Surface Activation of Amorphous Silica for Hydroxyl Bonding in TGV Applications	Interconnection Technologies	ACCEPT
614	Chenbing Qu, Yuanxin Yang, Zhiwei Fu, Bo Hou and Liwei Wang	Modeling and Analysis of Void Porosity Effects on Differential Mode Conversion in TGVs	Quality & Reliability	ACCEPT
616	Kaihong Hou, Zhengwei Fan, Yonggui Chen, Shufeng Zhang, Yashun Wang, Xiaofeng Yang and Xun Chen	Mechanism of Microstructural Evolution in TSVs under Thermo-Electrical-Mechanical Coupling: A Multi-Scale Crystal Plasticity Study	Quality & Reliability	ACCEPT
617	Jinsong Fang, Weijian Zhang, Lingshuang Hu, Li Zeng, Jingyu	Study on Heat Transfer and Phase Change Features of Metal Foam-Enhanced Phase Change Composites	Packaging Design & Modeling	ACCEPT
619	Yongqiang Li, Jing Lv, Xinghua Liu, Chaoyang Wang and Bing	Research and Performance Investigation of Thermal Stress Mitigation Buffer Layers for TGV Metallization	Interconnection Technologies	accept?
620	Minghao Tang, Fengze Hou, Meiying Su, Chen Peng and Chuan	Design Optimization of a Manifold Microchannel Cooling Module for a Three-Dimensional High-Compute AI Chip	Emerging Technologies	ACCEPT
621	Zexin Feng, Yingying Dou, Bo Yang, Qiming He, Zhengguang Jiang and Wenwen Kong	Packaging Design, Simulation and Fabrication of High-Precision Fast-Response Infrared Detectors with NTC Preheating Compensation Function	Emerging Technologies	ACCEPT
622	Tianning Deng, Wanchao Liu, Yonghui Ren, Wenwu Zhang and	Optimization of Pre-bonding Processes for Cu-SiO2 Hybrid Bonding	Interconnection Technologies	accept?
623	Xiaofei Pan, Arui Dai, Xiankun Zhang, Chaopeng Zhang, Dehua	Research on the Performance Impact of Top Heat Dissipation Packaging Structure	Packaging Materials & Processes	ACCEPT
625	Yonggui Chen, Zhengwei Fan, Kaihong Hou, Shufeng Zhang, Yashun Wang, Xiaofeng Yang and Xun Chen	Effect of cooling rates on microstructure and mechanical properties of TSV-Cu	Quality & Reliability	ACCEPT
626	Rongxu Cui, Xiangkun Yin, Fengjuan Wang, Qijun Lu and Tao	3D On-chip Integrated Capacitors with Self-inductance Cancellation for Wideband RF Application	RF Electronic Packaging	ACCEPT

627	Dongchen Fan, Xuesong Quan, Ningning Xu, Jingxiao Tang, Yi	Process Development and Suppression of Stress and Warpage	Emerging Technologies	ACCEPT
628	Xuesong Quan, Chen Yu, Peng Sun, Dongchen Fan and Daquan Yu	Highly Selective Fluorine-Free LIDE Process for High-Aspect-Ratio TGVs in Glass Interposers	Interconnection Technologies	accept?
629	Jinbao Zhang, Dongchen Fan, Yi Zhong and Daquan Yu	Achieving robust polycrystalline diamond-Si integration by ultra-thin film Ag-Ag bonding	Advanced Manufacturing	accept?
630	Changsi Wang, Ce Zeng, Dongyang Lei, Xin Kong, Kun Zhang,	Lifetime Modeling of GaAs pHEMT under Multi-Stress with Humidity	Quality & Reliability	ACCEPT
631	Yunhui Du, Zeming Tao, Dongchen Fan, Ke Li, Yi Zhong and Daquan Yu	Fabrication and Thermo-Mechanical Stress Optimization of High Aspect Ratio TSVs for Advanced 3D Integration	Interconnection Technologies	ACCEPT
632	Changsi Wang, Yang Li, Yangyang Li, Le Dong, Jian Zhang, Jiacheng Gao, Qian Lu, Xin Kong, Yanming Zhang and Weiwei	Scalable Equivalent Circuit Modeling and PDK Integration of Vertical Interconnects for 3D Ceramic Packages	Packaging Design & Modeling	ACCEPT
633	Bo Zhao, Yang Xi, Zhaochang Peng and Sheng Liu	Investigation of the Deposition Mechanism of Ta Barrier Layer Atoms on the Amorphous SiO2 Substrate from the Atomic	Interconnection Technologies	ACCEPT
636	Pengchao Wei, Xiangkun Yin, Fengjuan Wang, Tao Zhang and	A Compact Planar Fermat Spiral Inductor with High Self-Resonant Frequency for RF Integrated Applications	RF Electronic Packaging	ACCEPT
637	Hongming Liu, Yige Li, Qin Gu, Yipu Zhang, Jihong Liu, Jiliang Zhang and Lin Jiang	A Feature-Driven Approach for Chip Floorplan Inference Based on Dynamic Thermal Maps	Emerging Technologies	ACCEPT
639	Jianhao Wang, Jing Zhang, Yue Gao and Zhaoxi Chen	From Silver to Copper: An All-Sintered-Cu Interconnection for SiC Power Modules	Power Electronics & Energy Electronics	ACCEPT
640	Anqi Hu, Hongrui Liu, Yu Yang, Jialong Tang and Yunlong Li	Application of Surface Passivation Layer Technology in Al-Al Wafer Bonding	Interconnection Technologies	ACCEPT
641	Zifeng Ding, Zihong Gao, Yuanyuan Zhang, Tingting Dong and	Study on the Corrosion Behavior of Sintered Ag in Seawater	Packaging Materials & Processes	ACCEPT
642	Huaxiao Lu, Yingjun Zhang, Ruyan Zhang, Yijun Chen and Sha	Thermo-Mechanical Failure Analysis of Novel HDI Substrates for Millimeter-Wave Multi-Chip RF Front-End	Quality & Reliability	ACCEPT
644	Jiahao Zhu, Pan Liu and Xiaoguo Huang	Via S-Parameter Modeling for High-Speed Interconnects: A Physics-Guided Transformer-PINN with Experimental Calibration	AI-Enabled Packaging Technologies	ACCEPT

645	Bie Xiaorui, Zheng Wang, Kunfeng Wang, Wuhao Yang, Zhitian Li and Xudong Zou	Influence of viscoelastic behavior of die-attach adhesive on thermal stress and frequency stability of silicon resonant accelerometers	Quality & Reliability	ACCEPT
646	Chengyu Min, Wenya Zhang, Zhaohuan Tang, Sijie Tian, Chen Peng, Aopei Wang, Lingxia Tu and Sizhu Shao	Research on Design and Simulation of 3D Heterogeneous Integration for Optoelectronic Microsystems Based on TSV Silicon Bridges	Advanced Packaging	ACCEPT
647	Zheqi Xu, Qian Wang and Jian Cai	Interfacial Evolution and Electromigration Behavior of Cu–Ni–Cu–Sn Microbumps for Long-term Power Delivery in 3D	Quality & Reliability	ACCEPT
649	Haitao Fu, Jinglong Huang and Wei Yang	The effect of copper annealing on the fine line fabrication on IC substrate	Advanced Packaging	ACCEPT
650	Tang Feixiang, Zhou Zhaoxu, He Siyu, Zhan Ziqin, Liu Qiyin, Shu Qianyun, Xu Gaobin and Liu Sheng	Neural Network Model-Based Prediction of the Impact of Hard Particle Contaminants at Wafer Bonding Interfaces	Advanced Packaging	ACCEPT
652	Lu Tao, Xiaodong Chen and Hui Xiao	Dynamic Mechanical and Viscoelastic Behavior Analysis of Epoxy and Silicone Rubber Adhesives for Electronic Packaging Reinforcement	Packaging Materials & Processes	ACCEPT
653	Qihang Zong, Chenshan Gao and Huaiyu Ye	Systematic Investigation of Stencil Thickness and Drying Conditions in Large-Area Nano-Copper Sintering	Power Electronics & Energy Electronics	ACCEPT
654	Yong-Fu Zeng, Xing-Ping Zhang, Jia-Ao Chen and Zhen Sun	An Extensive Finite Element Simulation Study of the Interfacial Crack Propagation Behavior and the Kirkendall Void Effect in Sintered Cu Paste Joints with Different Metallization Layers under Thermo-Mechanical Loads	Quality & Reliability	ACCEPT
655	Zhe Sun, Zengxiong Zheng and Zhenfeng Xie	Failure Analysis on Vacuum Cleaner Caused by Electrostatic Discharge	Quality & Reliability	ACCEPT
656	Zhe Sun, Renxian Tao and Tianhan Liu	Precise Failure Localization of Integrated Circuits Through Comprehensive Multi-Analysis Approach	Quality & Reliability	ACCEPT
657	Xin Zhang, Yuxiang Zheng, Qidong Wang, Chenglin Yang, Quanlu Zhao, Pei Gan and Xinyu Zhang	A Low-Profile Wideband Circularly Polarized Integrated Antenna with Board-Level Packaging for K-Band Applications	RF Electronic Packaging	ACCEPT
658	Zhe Sun, Li Kuang and Haiwei Zeng	Case Study on Silver Migration Failure in Microelectronic Packaging	Quality & Reliability	ACCEPT
659	Ruihai Su, Xiangbin Du, Shuli Liu, Ao Li, Yifang Dong, Yanmei Kong and Binbin Jiao	Chip-level packaging solution with heterogeneous integration of vapor chamber	Advanced Packaging	ACCEPT

660	Xiangbin Du, Ruihai Su, Shuli Liu, Ao Li, Hangtian Zhu and Binbin Jiao	Monolithic electrodes and embedded cooling for minimizing interfacial thermal resistance in thermoelectric coolers	Advanced Packaging	ACCEPT
662	Yige Li, Hongming Liu, Qin Gu, Yipu Zhang, Jiliang Zhang and Lin Jiang	Runtime Power Map Prediction of Multicore Processors Driven	Emerging Technologies	ACCEPT
664	Wenyi Wang, Siliang He, Xingwen Qin, Yitian Sun, Jian Li and Qixuan Wang	Electro-Thermo-Mechanical Analysis of Cu Pillar/Sn Cap Microbumps for High-Density Packaging	Interconnection Technologies	ACCEPT
665	Xin Liao, Kai Xu, Jiangsen Luo, Bo Yi and Wenbo Luo	Thermal Distribution and Warpage Simulation of Ku-band GaN	Packaging Design & Modeling	ACCEPT
666	Guihai Li and Miao Cai	High-Temperature Reliability Characterization and Aging Verification of Silver Sintered Bodies Based on Resistivity-Temperature Response	Quality & Reliability	ACCEPT
667	Zihong Gao, Changhao Tan, Bin Chen, You Li, Li-Yin Gao, Caifu Li, Huicai Ma and Zhi-Quan Liu	Microstructure-Mimicking Cast Specimens for the Investigation of Reliability and Intrinsic Properties of Commercial Packaged Sn-xBi-yM Solder Joints	Packaging Materials & Processes	ACCEPT
668	Shun Xue, Feixiang Tang, Siyu He, Zhaoxu Zhou, Shizhao Wang and Sheng Liu	Numerical Reliability Assessment and Fatigue Life Extension of IGBT Modules Using Optimized Diamond/Metal Functionally	Quality & Reliability	ACCEPT
669	Yongjian Wang, Jiantao Liu, Guanghan Huang, Zihao Zheng, Bin Zeng, Yu Zhang, Guannan Yang, Chengqiang Cui and Kui	Numerical Study on the Thermal Performance of a 3D Stacked-Glass Substrate Packaging Structure with Embedded	Advanced Packaging	ACCEPT
670	Xiaokun Lin, Jixiang Zhu, Yujie Wang, Xiaoting Wang, Zhuolun Song, Zhixin Yue, Longxiang Yin, Ying Wang and Yinhe Han	Open-Source Benchmark Suite for Chiplet-based Advanced Packaging	Packaging Design & Modeling	ACCEPT
672	Anping Wang, Xiuqi Wang, Dashi Lu, Pengjie Zhou, Yuxuan Zhu and Hongjun Ji	Effect of Cu solute doping on microstructure and thermal stability of co-sputtered nanocrystalline-nanotwinned Ag-Cu films	Packaging Materials & Processes	ACCEPT
673	Weibin Hui, Kezhong Xu, Ziniu Yu, Yuxin Chen, Shibo Zu and Fulong Zhu	Temperature-Dependent Interfacial Thermal Resistance of GaN/AlN Heterostructures: Role of Ga/N Vacancy in the Near-Interface Region	Packaging Design & Modeling	ACCEPT
675	Tao Luo, Xin-Ping Zhang, Zhen Sun and Jia-Ao Chen	Computational Characterization of Interface Crack Initiation and Propagation in 16-Hi HBM4 with Hybrid Bonding TSV Structure under Thermo-mechanical Loads	Quality & Reliability	ACCEPT

676	Yangyang Yan, Haidong Liu, Peng Su, Cheng Xu, Fengwei Dai	Fabrication and Key Process Optimization of 2.5D CoWoS High	Packaging Materials & Processes	ACCEPT
678	Wei Luo, Hongming Zeng and Zhaohuan Tang	Design and Simulation of Multi-Channel High-Speed Optoelectronic Microsystem	Packaging Design & Modeling	ACCEPT
680	Meihong Zhao, Yizhou Han, Shuai Gong, Boxiang Wang, Jia Wei and Naiqian Zhang	Coupled thermo-mechanical analysis and reliability-oriented optimization of cylindrical pin-fin embedded microchannels for 3D-ICs	Packaging Design & Modeling	ACCEPT
683	Jiaqi Pang and Yingxin Cui	Study on Delamination Mechanism of Semi-Insulating SiC Single Crystal Substrates During High-Temperature Vacuum Reflow: Electro-Thermo-Mechanical Coupling Analysis	Advanced Packaging	ACCEPT
684	连乔 杨 and 伟选 袁	Optical Properties of Amorphous Si3N4: A First-Principles Investigation	Optoelectronics and New Display	ACCEPT
685	Zhaowei Jia, Qiqiang Wang and Meng Wu	Electroplating Filling of High Aspect Ratio TGV Under Decoupled Electric and Flow Fields	Advanced Packaging	ACCEPT
686	Dingjie Lu, Jun Liu, Zhuangjian Liu, Richard Xian-Ke Gao, Enxiao Liu, Mihai Rotaru, Dutta Rahul and Sridhar Narayanaswamy	Rapid Prediction of Orthotropic Coefficients of Thermal Expansion for 2.5D Chiplet Packaging RDL	AI-Enabled Packaging Technologies	ACCEPT
687	Shigao Chen, Qian Zhou, Hongqing Wei Wei and Guangjun Lu	High-Efficiency and Stable Green 3D/2D Perovskite Heterojunction PeLEDs Fabricated in Ambient Air	Optoelectronics and New Display	ACCEPT
688	Yanqi Li, Xia Huang and Sai Zhang	Laser-Patterned Periodic Microgrooves for Reducing Residual	Packaging Materials & Processes	ACCEPT
689	Yutao Li, Haotian Zhu, Jiaer Wu, Weizhong Huang, Yu Zhang and Chengqiang Cui	High Aspect Ratio Filling of Through-Glass Vias Using Copper Paste with Vacuum-Assisted Filtration	Advanced Manufacturing	ACCEPT
690	Zaijun Ye, Yanming Zhang, Can Sheng, Wansheng Wang, Shuo	Deep Learning-Accelerated Multi-Scale Thermo-Mechanical Simulation Framework for 3D Heterogeneous Integration	AI-Enabled Packaging Technologies	ACCEPT
691	Bin Chen, Qi Zhang, Zehao Zhao, Jiahong Wang and Zhi-Quan	Achieving high-strength copper-to-copper bonding with a low heat budget using electrodeposited columnar crystal Cu	Packaging Materials & Processes	ACCEPT
692	Yan Pan	A Study for Heterogeneous Integration of LED Chips onto Textiles via NCF Dielectric Layer and Solder-Based ACF Interconnections	Interconnection Technologies	reject?
694	Yizhe Ren, Fengjuan Wang, Zhuoyu Yang, Ningmei Yu, Yuan Yang, Hongwei Xie, Zhaonian Yang and Mingbin Yu	A Highly Selective Double-Layer SIW Bandpass Filter based on TSV Technology	Emerging Technologies	ACCEPT

695	Rui Zhou, Tong An and Fei Qin	Predictive Analysis of Low-to-High Cycle Fatigue Transition in Bond Wires of SiC Power Modules Under Different Junction Temperature Differences	Quality & Reliability	ACCEPT
696	Gui Chen, Wen Zhu and Xin-Ping Qu	Low Temperature Cu-Cu Direct Bonding Enabled by PVD-Deposited CoxN Passivation Layer	Advanced Packaging	ACCEPT
698	Hao Zhang, Liang Wang and Duanzheng Zhang	Cu-Au Direct Bonding with Surface Activated Coatings for SiC Power Module Packaging: An Ag-Free Interconnection Technology	Power Electronics & Energy Electronics	ACCEPT
699	Ruiting Zhang, Zhengxun Hu, Rong Sun and Zhao Liu	Property Regulation and Mechanism Analysis of Thin Films Prepared by TEOS-Based PECVD and Low-Temperature	Advanced Packaging	ACCEPT
700	Yulei Xie, Tong An and Fei Qin	Crack Propagation Behavior of Indium-Based Thermal Interface Material under Thermal Cycling	Quality & Reliability	ACCEPT
701	Ying Zhong	Application of Electrostatic Printing Technology in Embodied Intelligence-Oriented Flexible Sensors	Emerging Technologies	ACCEPT
702	Yachao Liu, Bin Ren, Bin Liu, Guangmin Zhang and Jie Wang	Cascaded Active Disturbance Rejection Control with Dual Disturbance Compensation for High-Precision Linear Motion Platform in White Light Interferometry	Advanced Manufacturing	ACCEPT
703	Jingsheng Liu, Baojun Qiu, Hui Tang and Jing Deng	The Component Level Reliability Verification of An Industrial Grade Analog to Digital Converter	Quality & Reliability	ACCEPT
705	Zhiwen Chen, Li Liu and 明 李	Structural and Porosity Characterization of Acetic Acid-Modulated Mg-MOF-74 for Low-k Dielectric Applications	Advanced Manufacturing	ACCEPT
706	Guangchao Lv, Xiaoyu Zhong, Peng Su, Cheng Xu, Yangyang	Process Development and Warpage Control of CoWoS-L Packaging Platform for High Performance Integrated Systems	Packaging Design & Modeling	ACCEPT
707	Yu-Yang Liu, Yu-Le Wang, Zhen Sun, Jia-Ao Chen and Xin-Ping Zhang	An In-depth Numerical Simulation Study on Interfacial Delamination and Cohesive Glass Fracture in Glass-Core Substrate Packages with Multi-Layer RDLs under Thermo-mechanical Loads	Quality & Reliability	ACCEPT
708	Hualong Fu, Jingyi Zhao, Meiying Su, Rui Ma, Quanlu Zhao, Chen Peng, Qidong Wang and Liqiang Cao	Effects of RVE-Based Homogenization Strategies on CoWoS-L	Advanced Packaging	ACCEPT
709	Chuang Yan, Jiaju Zhang, Haoze Luo, Bin Yu, Zhiwen Chen and Sheng Liu	Impact of Source Lead Structure and Material on Electro-Thermal-Mechanical Performance and Electromigration	Advanced Manufacturing	ACCEPT

710	Zhiqiao Ye and Rongbin Xu	Silicon-Based Three-Dimensional Deep Trench Capacitors with	Emerging Technologies	ACCEPT
711	Chao Li, Hao Li, Xuebao Li, Bo Zhao, Lei Wang, Wenyuan Li, Xu Zhang and Rui Jin	Shear Strength and Power Cycling Reliability of Nano-Silver Sintered Joints in Silicon Carbide MOSFET Power Modules	Quality & Reliability	ACCEPT
712	Yifan Su, Zhuo Chen, Menglin Tang, Xinwang Miao and Jiaxing	Atomic-Scale Investigation of Interfacial Healing Mechanisms in Indium-Indium Bonding	Interconnection Technologies	ACCEPT
714	Chuangwei Ma, Jianxiong Zou, Li Liu, Tingrui Gong, Xiaojia Luo, Jianping Zeng and Junze Li	Integration of GaN and single-crystal diamond via low-temperature atomic diffusion bonding	Interconnection Technologies	reject?
715	Wei Li	Warpage Study of Heterogeneous Integration in Die-first and Die-last FOWLP	Packaging Materials & Processes	ACCEPT
718	Lin Xing, Ruzhi Wang, Han Wang and Jinglin Fan	Study on the Warpage Characteristics and Reliability of Fan-Out Panel-Level Packaging Based on EMC Materials	Packaging Materials & Processes	ACCEPT
719	Yang Qiao and Kangrong Li	Signal Integrity Analysis and Optimization of Silicon-Based 3D Heterogeneous Integrated High-Speed Interconnects	Packaging Design & Modeling	ACCEPT
720	Zhiyang Lin, Minbo Zhou, Jianyun Qin, Bin Hou and Xinping Zhang	Preparation and Protective Performance of Superhydrophobic Coatings on PCB Assemblies Based on Highly Dispersed Nanosilica-Organic Systems	Packaging Materials & Processes	ACCEPT
721	Changhao Chen, Tianming Sun, Hengtong Guo, Xiaochen Xie,	High-Precision Spatiotemporal Energy Modulation in Laser-Assisted Bonding Enabling High-Reliability Packaging	Interconnection Technologies	ACCEPT
722	Xin-Ping Zhang, Hai-Ping Li, Yang-Lei Zhu, Jian-Wei Xian and Xiao Ma	High-Uniformity Large-Area Photoresist Removal Based on Optimization of Inductively Coupled Plasma (ICP) Source Architecture for Advanced Fan-out Panel-Level Packaging	Advanced Manufacturing	ACCEPT
723	Xin-Ping Zhang, Jian-Wei Xian, Hai-Ping Li, Yang-Lei Zhu and Xiao Ma	Dual-scale Modelling of Microwave Remote Plasma System for Enhancing Photoresist Stripping Uniformity in Large-Area	Advanced Manufacturing	ACCEPT
724	Ting Li, Hui Xia, Jiaxiaolong Li, Xiaobo Hu and Xiaojun Zhang	Hybrid Dual-Frequency Capacitively Coupled Plasma/Inductively Coupled Plasma Etching for Sidewall Roughening of Through-Glass Vias to Enhance Adhesion Strength	Interconnection Technologies	accept?
725	Yuan Yuan, Chen Zhiwen and Liu Li	Morphology Evolution of Laser-Induced Carbon Residues in Wafer Debonding	Advanced Packaging	ACCEPT

729	Shicheng Shan, Linfeng Chen, Jingwen Zang, Shimeng Xu, Xiaochen Xie and Pengrong Lin	Simulation and Experimental Study on the Highly Reliable Structural Design of Organic Substrate Stacked Holes	Quality & Reliability	ACCEPT
730	Jiangsen Luo, Jingyang Cao, Kai Xu, Ruyi Li, Bo Yi, Wenbo Luo and Wanli Zhang	Design and Analysis of a Flip-Chip SiP TR Module with High Heat Dissipation Performance	Packaging Design & Modeling	ACCEPT
731	Xiang Chen, Haiyang Li, Yao Cai and Chengliang Sun	Wafer-Level Thin-Film Packaging for 2.4 GHz Film Bulk Acoustic Resonator Filters	RF Electronic Packaging	ACCEPT
732	Tingting Huang, Yunhui Zhu, Jiaqiang Huang, Xudong Wang and	Near-in situ observation of the effect of electromigration on microstructural evolution of hybrid solder joints	Quality & Reliability	ACCEPT
733	Yang-Lei Zhu, Hai-Ping Li, Jian-Wei Xian, Xiao Ma and Xing-Ping Zhang	Simulation Study and Experimental Validation for Optimization of Gas Distribution Plate Structure and Improvement of Plasma Photoresist Stripping in Fan-out Panel-level Packaging (FOPLP)	Advanced Manufacturing	accept?
734	Jian-Wei Xian, Yang-Lei Zhu, Hai-Ping Li, Xiao Ma and Xing-Ping Zhang	Combined Experimental and Simulation Studies of a Multi-Parameter Coupled Microwave Plasma Process for High-Rate and Uniform Wafer-Level Photoresist Stripping	Advanced Manufacturing	ACCEPT
735	Bingfeng Guo, Yifan Xu, Kangyou Li, Yuena Sun, Liming Liu and Xuepeng Li	Growth Mechanism of Interfacial Intermetallic Compounds in Sn-Bi/Cu soldering joints under Different Soldering Processes	Quality & Reliability	ACCEPT
736	Zhang Yuan, Wei Suhang, Lv Weishan, Yang Liu, Liu Jiaxin and Chen Cai	A Novel High-Reliability Press-Pack IGBT Power Device Based	Power Electronics & Energy Electronics	ACCEPT
737	Huan Liu, Shaou Wang, Lv Zhijun, Fei Wang and Xiangyu Sun	Thermo-mechanical Reliability Simulation and Experimental Validation for Microsystem Packaging Based on Solder Balls	Quality & Reliability	ACCEPT
741	Chengjun Wang, Jingguo Zhang, Zhanrong Li, Limin Wang, Shanyu Han, Dan Qin, Ning Wang and Yu Ma	Controlled One-Pot Synthesis of Copper Nanospheres through	Packaging Materials & Processes	ACCEPT
742	Yilan Guo, Zhaoyu Lin, Longfeng Zou, Yucheng Jiang, Taoying Rao, Yimin Yao, Pengli Zhu and Rong Sun	Design of Poly(ionic liquid)/Silver–Liquid Metal Composites for High-Performance Silicone-Free Thermal Interface Materials	Packaging Materials & Processes	ACCEPT
744	Haitian Zhou and Kai-Da Xu	An Evanescent-Mode Rectangular Waveguide Bandpass Filter	RF Electronic Packaging	ACCEPT
745	Jiabo Zhang, Zhixian Min, Li Zhang, Desheng Xing and Xueqiang Jia	Research on solderability test method of ceramic ball grid array encapsulation devices	Quality & Reliability	ACCEPT

746	Peijiang Liu, Junhao Liang, Bingxu Ma, Wanchun Tian, Xiaodong Jian, Si Chen, Xiaofeng Yang and Weiming Li	Open-Circuit Failure Analysis of a Plastic-Encapsulated DDR Device in an Automotive Multimedia System	Quality & Reliability	